

DSC-HX50/HX50V

SERVICE MANUAL

Ver. 1.0 2013.04



Photo: DSC-HX50V/Black

LEVEL 3

- US Model*
- Canadian Model*
- AEP Model*
- UK Model*
- Russian Model*
- E Model*
- Australian Model*
- Hong Kong Model*
- Chinese Model*
- Korea Model*
- Brazilian Model*
- Japanese Model*

Check the SERVICE NOTE (LEVEL 2) before the service.

Revision History

Ver.	Date	History	Contents	S.M. Rev. issued
1.0	2013.04	Official Release	—	—

The components identified by mark Δ or dotted line with mark Δ are critical for safety. Replace only with part number specified.

Les composants identifiés par une marque Δ sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

DIGITAL STILL CAMERA
SONY[®]

Caution

Danger of explosion if battery is incorrectly replaced.
Replace only with the same or equivalent type.
Dispose of used batteries according to the instructions.

SAFETY-RELATED COMPONENT WARNING!!

COMPONENTS IDENTIFIED BY MARK \triangle OR DOTTED LINE WITH MARK \triangle ON THE SCHEMATIC DIAGRAMS AND IN THE PARTS LIST ARE CRITICAL TO SAFE OPERATION. REPLACE THESE COMPONENTS WITH SONY PARTS WHOSE PART NUMBERS APPEAR AS SHOWN IN THIS MANUAL OR IN SUPPLEMENTS PUBLISHED BY SONY.

ATTENTION AU COMPOSANT AYANT RAPPORT À LA SÉCURITÉ!

LES COMPOSANTS IDENTIFIÉS PAR UNE MARQUE \triangle SUR LES DIAGRAMMES SCHÉMATIQUES ET LA LISTE DES PIÈCES SONT CRITIQUES POUR LA SÉCURITÉ DE FONCTIONNEMENT. NE REMPLACER CES COMPOSANTS QUE PAR DES PIÈCES SONY DONT LES NUMÉROS SONT DONNÉS DANS CE MANUEL OU DANS LES SUPPLÉMENTS PUBLIÉS PAR SONY.

SAFETY CHECK-OUT

After correcting the original service problem, perform the following safety checks before releasing the set to the customer.

1. Check the area of your repair for unsoldered or poorly-soldered connections. Check the entire board surface for solder splashes and bridges.
2. Check the interboard wiring to ensure that no wires are “pinched” or contact high-wattage resistors.
3. Look for unauthorized replacement parts, particularly transistors, that were installed during a previous repair. Point them out to the customer and recommend their replacement.
4. Look for parts which, through functioning, show obvious signs of deterioration. Point them out to the customer and recommend their replacement.
5. Check the B+ voltage to see it is at the values specified.
6. Flexible Circuit Board Repairing
 - Set the soldering iron tip temperature to 350 °C approximately.
 - Do not touch the soldering iron on the same conductor of the circuit board (within 3 times).
 - Be careful not to apply force on the conductor when soldering or unsoldering.

UNLEADED SOLDER

This unit uses unleaded solder.
Boards requiring use of unleaded solder are printed with the lead free mark (LF) indicating the solder contains no lead.
(Caution: Some printed circuit boards may not come printed with the lead free mark due to their particular size.)



LF : LEAD FREE MARK

Be careful to the following points to solder or unsolder.

- Set the soldering iron tip temperature to 350 °C approximately.
If cannot control temperature, solder/unsolder at high temperature for a short time.
Caution: The printed pattern (copper foil) may peel away if the heated tip is applied for too long, so be careful!
Unleaded solder is more viscous (sticky, less prone to flow) than ordinary solder so use caution not to let solder bridges occur such as on IC pins, etc.
- Be sure to control soldering iron tips used for unleaded solder and those for leaded solder so they are managed separately. Mixing unleaded solder and leaded solder will cause detachment phenomenon.

注意

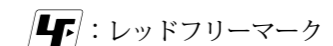
電池の交換は、正しく行わないと破裂する恐れがあります。電池を交換する場合には必ず同じ型名の電池又は同等品と交換してください。使用済み電池は、取扱指示に従って処分してください。

サービス、点検時には次のことにご注意ください。

1. 注意事項をお守りください。
サービスのとき特に注意を要する個所については、キャビネット、シャーシ、部品などにラベルや捺印で注意事項を表示しています。これらの注意書き及び取扱説明書等の注意事項を必ずお守り下さい。
2. 指定部品のご使用を
セットの部品は難燃性や耐電圧など安全上の特性を持ったものとなっています。従って交換部品は、使用されていたものと同じ特性の部品を使用して下さい。特に回路図、部品表に \triangle 印で指定されている安全上重要な部品は必ず指定のものをご使用下さい。
3. 部品の取付けや配線の引きまわしはもとどおりに
安全上、チューブやテープなどの絶縁材料を使用したり、プリント基板から浮かして取付けた部品があります。また内部配線は引きまわしやクランプによって発熱部品や高圧部品に接近しないよう配慮されていますので、これらは必ずもとどおりにして下さい。
4. サービス後は安全点検を
サービスのために取外したネジ、部品、配線がもとどおりになっているか、またサービスした個所の周辺を劣化させてしまったところがないかなどを点検し、安全性が確保されていることを確認して下さい。
5. チップ部品交換時の注意
 - 取外した部品は再使用しないで下さい。
 - タンタルコンデンサのマイナス側は熱に弱いため交換時は注意して下さい。
6. フレキシブルプリント基板の取扱いについて
 - 半田こてのこて先温度は約350°Cに設定してください。
 - 同一パターンに何度もコテ先を当てないで下さい。(3回以内)
 - パターンに力が加わらないよう注意して下さい。

無鉛半田について

本機には無鉛半田が使用されています。無鉛半田を使用している基板には、無鉛(Lead Free)を意味するレッドフリーマークがプリントされています。(注意：基板サイズによっては、無鉛半田を使用してもレッドフリーマークがプリントされていないものがあります)



LF : レッドフリーマーク

無鉛半田は、下記の点に注意して使用してください。

- 半田こてのこて先温度は約350°Cに設定してください。温度調節が無理な場合は、高温短時間で作業を行ってください。
注意：半田こてを長く当てすぎると、基板のパターン(銅箔)がはがれてしまうことがありますので、注意してください。また、従来の半田よりも粘性が強いため、IC端子などが半田ブリッジしないように注意してください。
- 半田こてのこて先は、必ず無鉛半田用と有鉛半田用に分けて管理してください。無鉛半田と有鉛半田が混在すると剥離現象が発生してしまいます。

2. REPAIR PARTS LIST

BT-2006
CD-1005
FL-2000
MS-505
MS-1013
RL-1011

(ENGLISH)

- NOTE:**
- XX, -X mean standardized parts, so they may have some differences from the original one.
 - Items marked "*" are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
 - The mechanical parts with no reference number in the exploded views are not supplied.
 - Due to standardization, replacements in the parts list may be different from the parts specified in the diagrams or the components used on the set.
 - CAPACITORS:**
uF: μF
COILS
uH: μH
 - RESISTORS**
All resistors are in ohms.
METAL: metal-film resistor
METAL OXIDE: Metal Oxide-film resistor
F: nonflammable
 - SEMICONDUCTORS**
In each case, u: μ, for example:
uA..., uPA..., uPA..., uPA...,
uPB..., uPB..., uPC..., uPC...,
uPD..., uPD...

When indicating parts by reference number, please include the board name.

The components identified by mark Δ or dotted line with mark Δ are critical for safety. Replace only with part number specified.

Les composants identifiés par une marque Δ sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

Caution
Danger of explosion if battery is incorrectly replaced. Replace only with the same or equivalent type. Dispose of used batteries according to the instructions.

Note : Be sure to read "Precautions for Replacement of Imager" on page 6-1.

(JAPANESE)

- 【使用上の注意】**
- ここに記載されている部品は、補修用部品であるため、回路図及びセットに付いている部品と異なる場合があります。
 - XX, -Xは標準化部品のため、セットに付いている部品と異なる場合があります。
 - *印の部品は常備在庫しておりません。
 - コンデンサの単位でuFはμFを示します。
 - 抵抗の単位Ωは省略してあります。
金 被：金属被膜抵抗。
サンキン：酸化金属被膜抵抗。
 - インダクタの単位でuHはμHを示します。
 - 半導体の名称でuA..., uPA..., uPB..., uPC..., uPD...等はそれぞれμA..., μPA..., μPB..., μPC..., μPD...を示します。

お願い
図面番号で部品を指定するときは基板名又はブロックを併せて指定してください。

Δ印の部品、またはΔ印付の点線で囲まれた部品は、安全性を維持するために、重要な部品です。従って交換時は、必ず指定の部品を使用してください。

注意
電池の交換は、正しく行わないと破裂する恐れがあります。電池を交換する場合には必ず同じ型名の電池又は同等品と交換してください。使用済み電池は、取扱指示に従って処分してください。

Note : イメージャの交換時は6-1ページの「イメージャ交換時の注意」を必ずお読みください。

2-2. ELECTRICAL PARTS LIST

Ref. No.	Part No.	Description
	A-1940-468-A	BT-2006 FLEXIBLE BOARD, COMPLETE *****
(BT001 is not included in BT-2006 FLEXIBLE COMPLETE BOARD (SERVICE).)		
< BATTERY >		
△ BT001	1-756-813-11	LITHIUM RECHARGEABLE BATTERY
< CAPACITOR >		
C101	1-118-417-11	CERAMIC CHIP 0.1uF 10% 16V
C102	1-116-713-11	CERAMIC CHIP 22uF 20% 10V
△* C104	1-116-456-11	CERAMIC CHIP 0.047uF 10% 350V
△ C105	1-100-761-21	CERAMIC CHIP 0.01uF 10% 250V
< CONNECTOR >		
* CN101	1-816-650-51	FFC/FPC CONNECTOR (LIF) 24P
< DIODE >		
* D001	6-501-861-01	DIODE CL-360S-TD4-X-TL
△* D101	6-503-901-01	DIODE DA2JF6500L
△* D102	6-503-001-01	DIODE RR255M-400FJTR
< IC >		
IC101	6-716-806-01	IC R2J20071DNS
< COIL >		
* L101	1-400-820-11	INDUCTOR 2.2uH
< TRANSISTOR >		
△ Q101	6-552-987-01	TRANSISTOR RJP4010AGE-01
< RESISTOR >		
R001	1-218-945-11	METAL CHIP 220 5% 1/16W
R101	1-218-871-11	METAL CHIP 10K 0.5% 1/10W
R102	1-208-889-11	METAL CHIP 1.2K 0.5% 1/16W
R103	1-208-643-11	METAL CHIP 22 0.5% 1/16W
R104	1-218-941-11	METAL CHIP 100 5% 1/16W
△ R105	1-216-121-11	METAL CHIP 1M 5% 1/10W
R106	1-216-097-11	METAL CHIP 100K 5% 1/10W
< TRANSFORMER >		
△* T101	1-445-749-21	D.C.-D.C.CONVERTER TRANSFORMER

	A-1940-465-A	CD-1005 FLEXIBLE BOARD, COMPLETE *****
(All mounted parts are not supplied, but they are included in CD-1005 FLEXIBLE COMPLETE BOARD.)		

△	A-1955-498-A	SERVICE (BLACK), ST BLOCK ASSY (BLACK)
△	A-1955-499-A	SERVICE (SILVER), ST BLOCK ASSY (SILVER)
	(Not supplied)	FL-2000 FLEXIBLE BOARD *****
(FL-2000 FLEXIBLE BOARD are not supplied, but they are included in ST BLOCK ASSY (SERVICE).)		

Ref. No.	Part No.	Description
	1-886-328-11	MS-505 FLEXIBLE BOARD *****

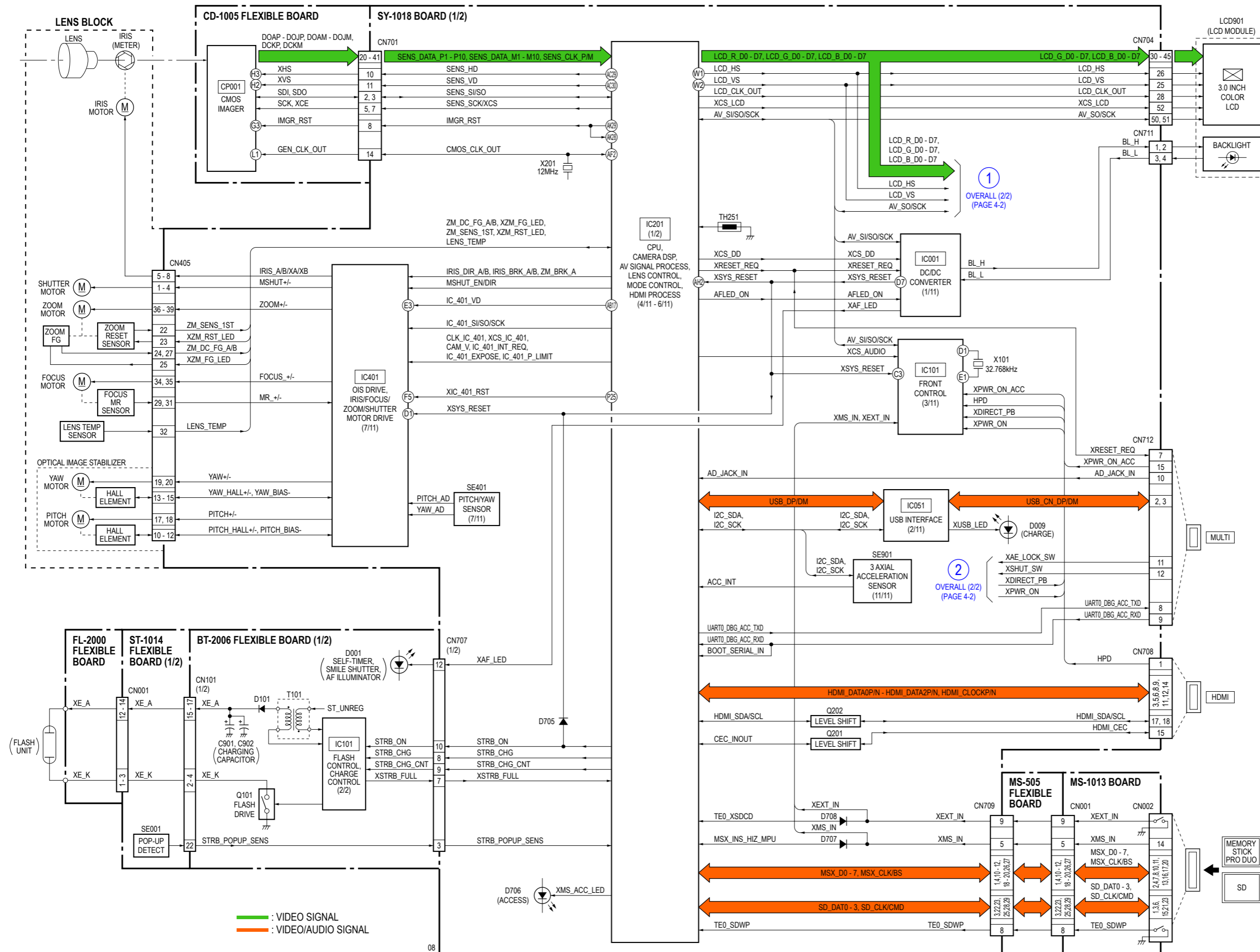
	A-1940-464-A	MS-1013 BOARD, COMPLETE *****
< CONNECTOR >		
* CN001	1-821-502-11	CONNECTOR, FPC (ZIF) 29P
CN002	1-843-088-12	CARD CONNECTOR
< RESISTOR >		
R001	1-218-990-81	SHORT CHIP 0
R002	1-218-937-11	METAL CHIP 47 5% 1/16W

	A-1940-736-A	RL-1011 BOARD, COMPLETE (SERVICE) (HX50V)
	A-1940-463-A	RL-1011 BOARD, COMPLETE (HX50) *****
(ANT402, C108, C401, C416, C417, C427, C429, ET401, IC001, IC402, IC404, L403, R412, S003, SE001 and SWF002 are not supplied, but they are included in RL-1011 COMPLETE BOARD (SERVICE).)		
< ANTENNA >		
ANT402	(Not supplied)	GPS ANTENNA (HX50V)
< CAPACITOR >		
* C101	1-118-407-11	CERAMIC CHIP 470PF 10% 50V
C102	1-118-417-11	CERAMIC CHIP 0.1uF 10% 16V
C103	1-118-417-11	CERAMIC CHIP 0.1uF 10% 16V
C104	1-118-388-11	CERAMIC CHIP 0.047uF 10% 25V
C105	1-118-417-11	CERAMIC CHIP 0.1uF 10% 16V
C106	1-118-388-11	CERAMIC CHIP 0.047uF 10% 25V
* C107	1-116-714-11	CERAMIC CHIP 22uF 20% 6.3V
C108	(Not supplied)	CERAMIC CHIP 4.7uF 10% 6.3V
C109	1-114-411-21	CERAMIC CHIP 0.33uF 10% 6.3V
C401	(Not supplied)	CERAMIC CHIP 1.8PF 0.1PF 25V (HX50V)
C403	1-116-741-11	CERAMIC CHIP 0.47uF 20% 10V (HX50V)
C404	1-116-743-11	CERAMIC CHIP 0.22uF 10% 16V (HX50V)
C408	1-118-417-11	CERAMIC CHIP 0.1uF 10% 16V (HX50V)
C409	1-118-417-11	CERAMIC CHIP 0.1uF 10% 16V (HX50V)
C410	1-116-724-11	CERAMIC CHIP 4.7uF 20% 6.3V (HX50V)
C411	1-128-605-11	CERAMIC CHIP 12PF 5% 25V (HX50V)
C412	1-128-605-11	CERAMIC CHIP 12PF 5% 25V (HX50V)
C413	1-116-153-11	CERAMIC CHIP 18PF 1% 50V (HX50V)
C414	1-116-720-11	CERAMIC CHIP 10uF 20% 6.3V (HX50V)
* C415	1-116-738-11	CERAMIC CHIP 1uF 10% 6.3V (HX50V)
C416	(Not supplied)	CERAMIC CHIP 0.01uF 10% 16V (HX50V)
C417	(Not supplied)	CERAMIC CHIP 2.2PF 0.1PF 50V (HX50V)
* C418	1-118-458-11	CERAMIC CHIP 0.1uF 10% 6.3V (HX50V)
C419	1-116-732-11	CERAMIC CHIP 2.2uF 20% 6.3V (HX50V)
C420	1-116-732-11	CERAMIC CHIP 2.2uF 20% 6.3V (HX50V)
C421	1-116-875-91	CERAMIC CHIP 1uF 20% 6.3V (HX50V)
C423	1-116-875-91	CERAMIC CHIP 1uF 20% 6.3V (HX50V)
C424	1-116-875-91	CERAMIC CHIP 1uF 20% 6.3V (HX50V)
C425	1-116-875-91	CERAMIC CHIP 1uF 20% 6.3V (HX50V)
C426	1-127-991-91	CERAMIC CHIP 2PF 0.25PF 25V (HX50V)
C427	(Not supplied)	CERAMIC CHIP 0.001uF 10% 25V (HX50V)

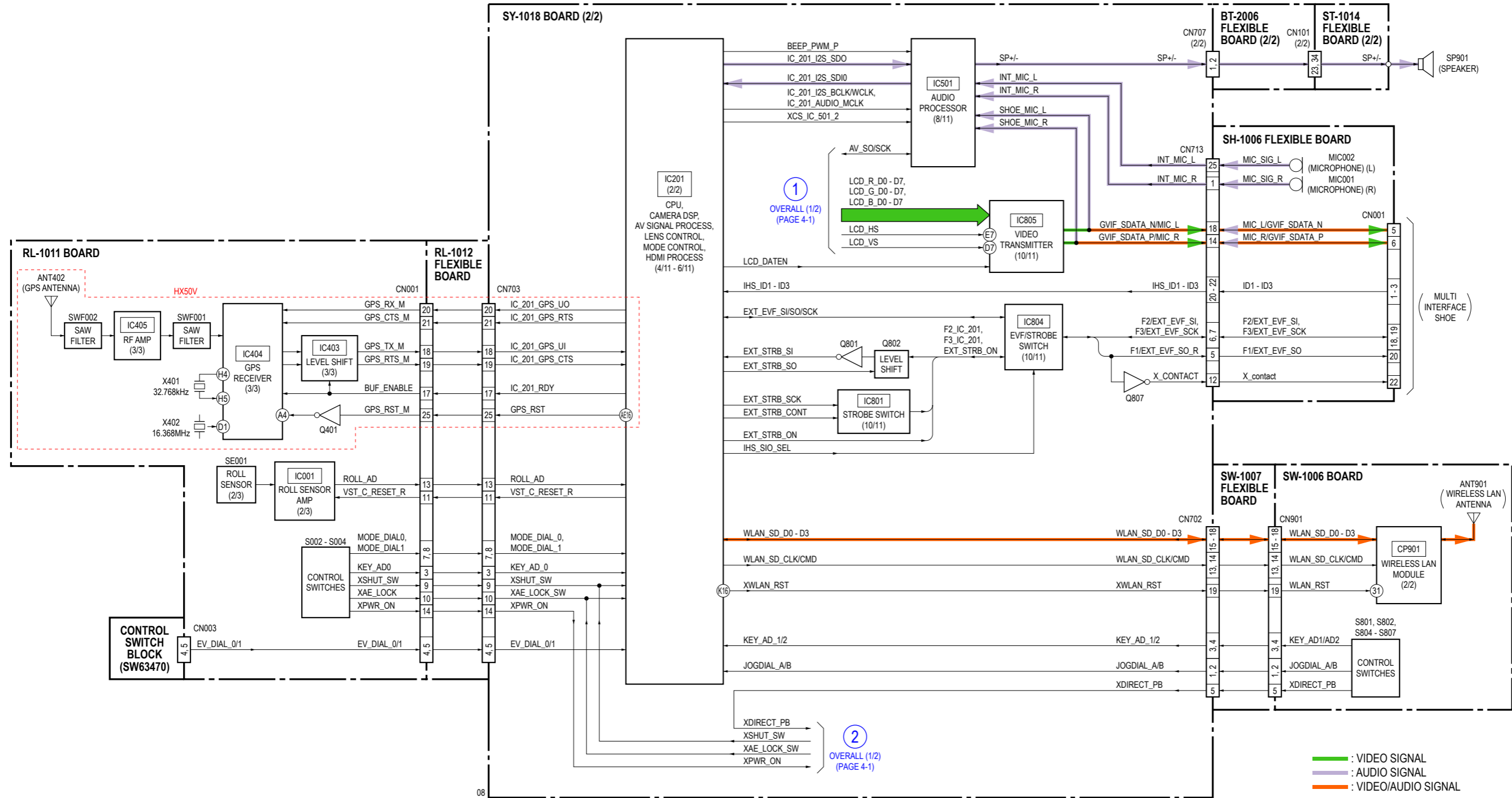
Ref. No.	Part No.	Description			
R706	1-218-945-11	METAL CHIP	220	5%	1/16W
R710	1-240-695-91	METAL CHIP	1K	5%	1/20W
R735	1-218-953-11	METAL CHIP	1K	5%	1/16W
R801	1-240-718-91	METAL CHIP	100K	5%	1/20W
R802	1-240-701-91	METAL CHIP	3.3K	5%	1/20W
R804	1-240-701-91	METAL CHIP	3.3K	5%	1/20W
R809	1-240-718-91	METAL CHIP	100K	5%	1/20W
R810	1-240-703-91	METAL CHIP	4.7K	5%	1/20W
R813	1-240-683-91	METAL CHIP	100	5%	1/20W
R814	1-240-718-91	METAL CHIP	100K	5%	1/20W
R815	1-240-714-91	METAL CHIP	47K	5%	1/20W
R817	1-240-729-91	METAL CHIP	1M	5%	1/20W
R822	1-250-495-11	METAL CHIP	1K	1%	1/16W
R823	1-220-803-81	METAL CHIP	4.7	5%	1/16W
R825	1-218-941-81	METAL CHIP	100	5%	1/16W
R826	1-218-941-81	METAL CHIP	100	5%	1/16W
R838	1-218-953-11	METAL CHIP	1K	5%	1/16W
R839	1-218-977-11	METAL CHIP	100K	5%	1/16W
R840	1-218-985-11	METAL CHIP	470K	5%	1/16W
R841	1-218-985-11	METAL CHIP	470K	5%	1/16W
< COMPOSITION CIRCUIT BLOCK >					
RB251	1-234-702-11	RES, NETWORK	68 (1005X4)		
RB252	1-234-702-11	RES, NETWORK	68 (1005X4)		
RB253	1-234-702-11	RES, NETWORK	68 (1005X4)		
RB254	1-234-702-11	RES, NETWORK	68 (1005X4)		
RB255	1-234-702-11	RES, NETWORK	68 (1005X4)		
RB256	1-234-702-11	RES, NETWORK	68 (1005X4)		
RB257	1-234-381-11	RES, NETWORK	100K (1005X4)		
RB258	1-234-378-21	RES, NETWORK	10K (1005X4)		
RB259	1-234-371-11	RES, NETWORK	47 (1005X4)		
RB260	1-234-371-11	RES, NETWORK	47 (1005X4)		
RB261	1-234-373-21	RES, NETWORK	220 (1005X4)		
RB262	1-234-372-11	RES, NETWORK	100 (1005X4)		
< SENSOR >					
SE401	8-826-002-51	GYRO SENSOR GSU-X370D/N-S(1) (PITCH/YAW)			
SE901	1-490-064-22	SENSOR 3 AXIAL ACCELERATION			
< THERMISTOR >					
TH251	1-805-194-21	THERMISTOR, NTC (SMD)			
< VIBRATOR >					
X101	1-795-602-61	VIBRATOR, CRYSTAL (32.768kHz)			
X201	1-487-897-31	SILICON OSCILLATOR (12MHz)			

4. BLOCK DIAGRAMS

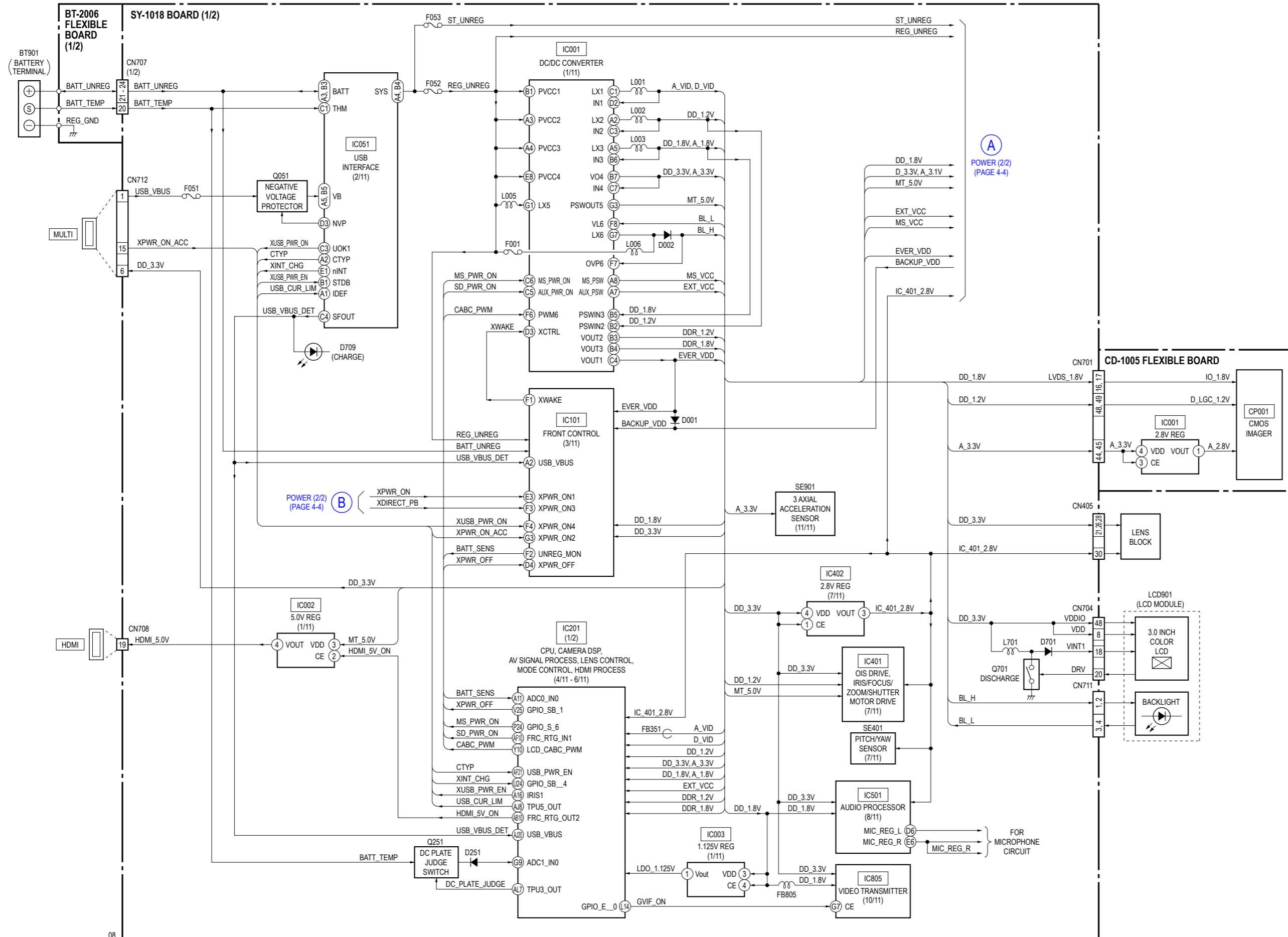
4-1. OVERALL BLOCK DIAGRAM (1/2) () : Number in parenthesis () indicates the division number of schematic diagram where the component is located.



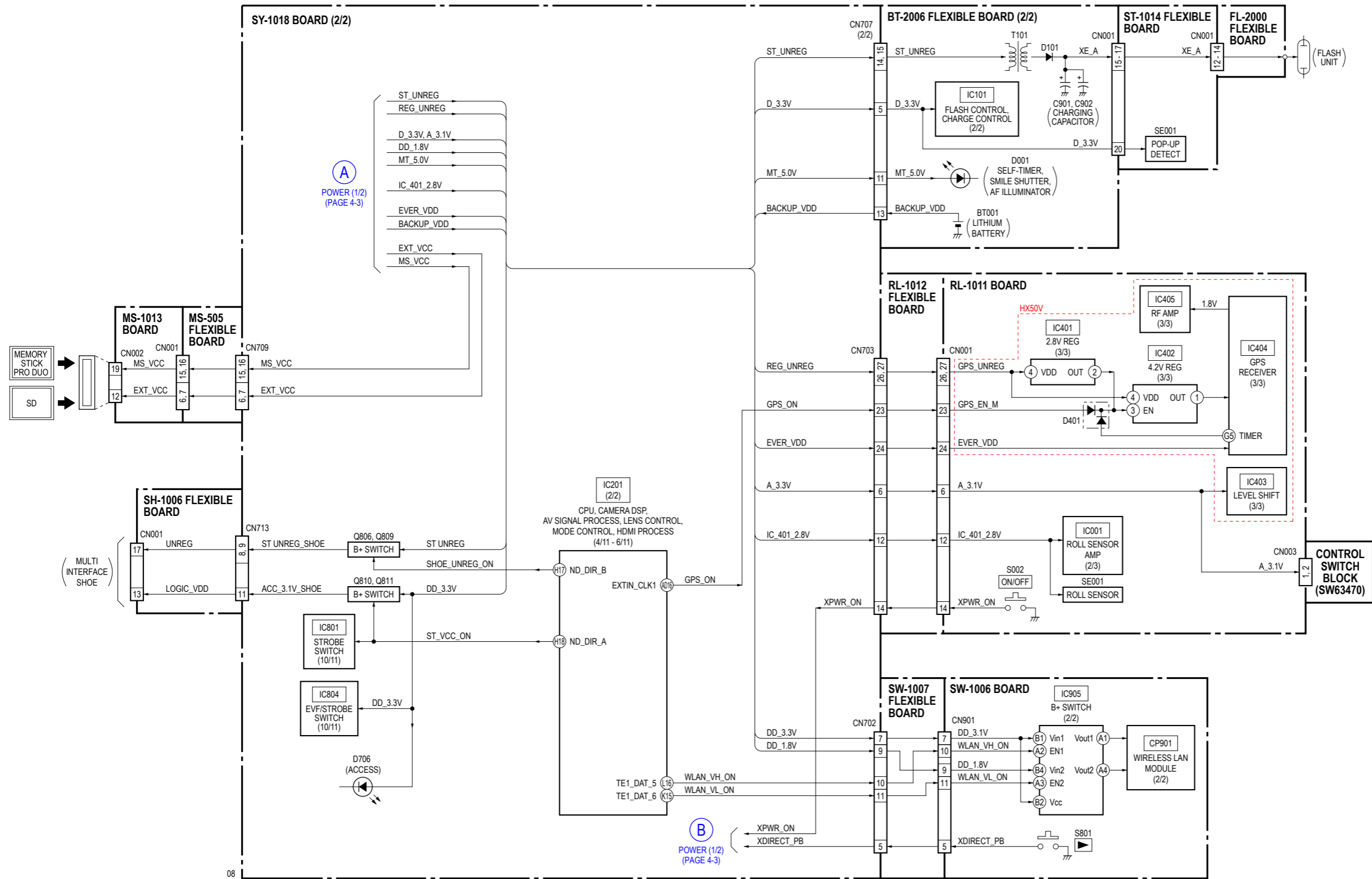
4-2. OVERALL BLOCK DIAGRAM (2/2) () : Number in parenthesis () indicates the division number of schematic diagram where the component is located.



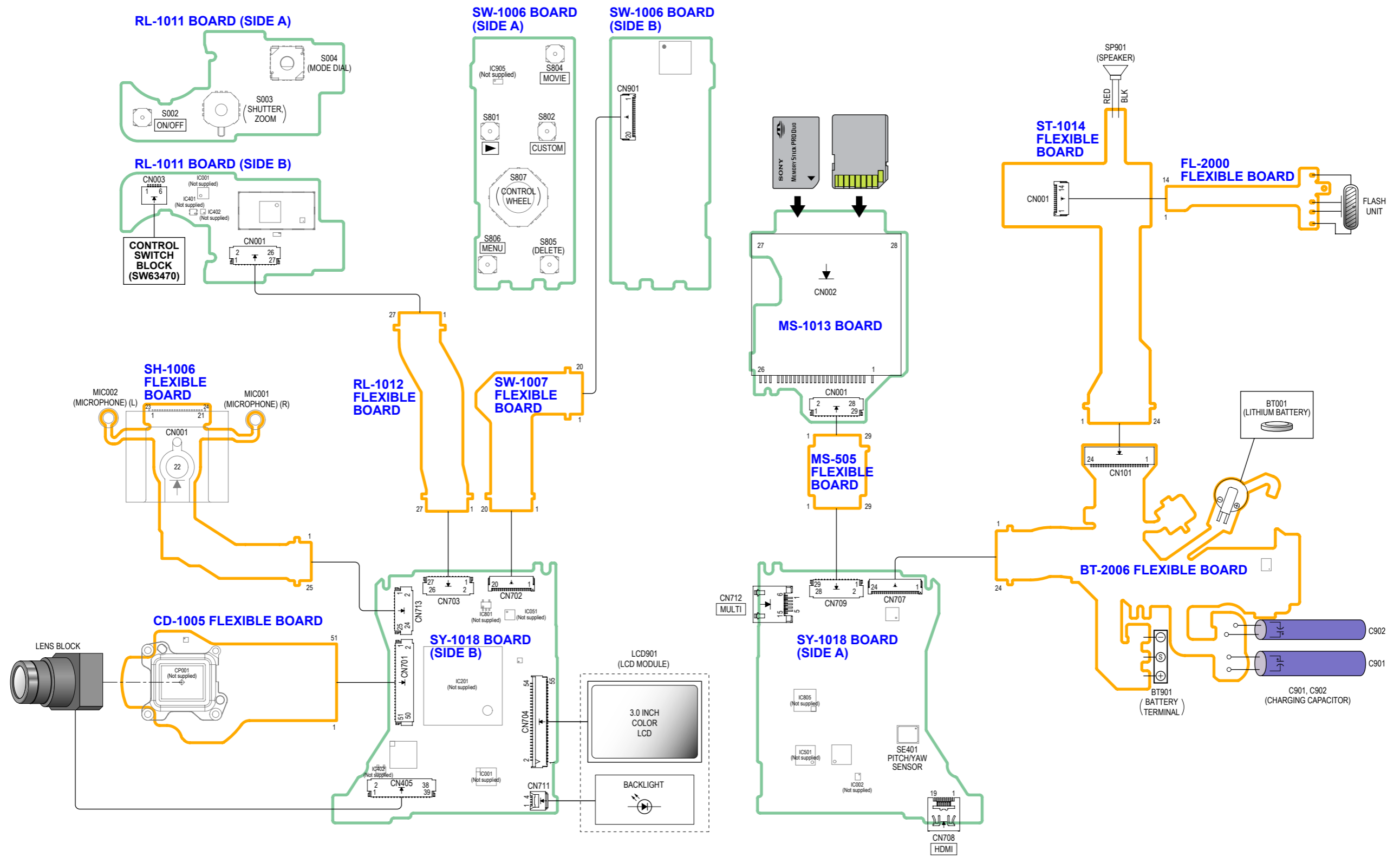
4-3. POWER BLOCK DIAGRAM (1/2) () : Number in parenthesis () indicates the division number of schematic diagram where the component is located.



4-4. POWER BLOCK DIAGRAM (2/2) () : Number in parenthesis () indicates the division number of schematic diagram where the component is located.



5. FRAME SCHEMATIC DIAGRAMS



6. SCHEMATIC DIAGRAMS AND PRINTED WIRING BOARDS

- ENGLISH -

THIS NOTE IS COMMON FOR SCHEMATIC DIAGRAMS AND PRINTED WIRING BOARDS.
(In addition to this, the necessary note is printed in each block.)

For Schematic Diagrams

- All capacitors are in μF unless otherwise noted. $\text{pF} : \mu\text{F} \cdot 50$ V or less are not indicated except for electrolytics and tantalums.
- Chip resistors are 1/10 W unless otherwise noted. $\text{k}\Omega=1000 \Omega$, $\text{M}\Omega=1000 \text{k}\Omega$.
- Caution when replacing chip parts.
New parts must be attached after removal of chip.
Be careful not to heat the minus side of tantalum capacitor, Because it is damaged by the heat.
- Some chip part will be indicated as follows.

Example	C541	L452
	22U	10UH
	TA A	2520
	TA	A
	22U	10UH
	TA	A
	2520	

Kinds of capacitor External dimensions (mm)
Case size

- Constants of resistors, capacitors, ICs and etc with XX indicate that they are not used.
In such cases, the unused circuits may be indicated.
- Parts with ★ differ according to the model/destination.
Refer to the mount table for each function.
- All variable and adjustable resistors have characteristic curve B, unless otherwise noted.
- Signal name
XEDIT → $\overline{\text{EDIT}}$ PB/XREC → $\overline{\text{PB/REC}}$
- : non flammable resistor
- : fusible resistor
- : panel designation
- : B+ Line
- : B- Line
- : IN/OUT direction of (+, -) B LINE.
- : adjustment for repair.

Precautions for Replacement of Imager

- If the imager has been replaced, carry out all the adjustments for the camera section.
- As the imager may be damaged by static electricity from its structure, handle it carefully like for the MOS IC.
In addition, ensure that the receiver is not covered with dusts nor exposed to strong light.

When indicating parts by reference number, please include the board name.

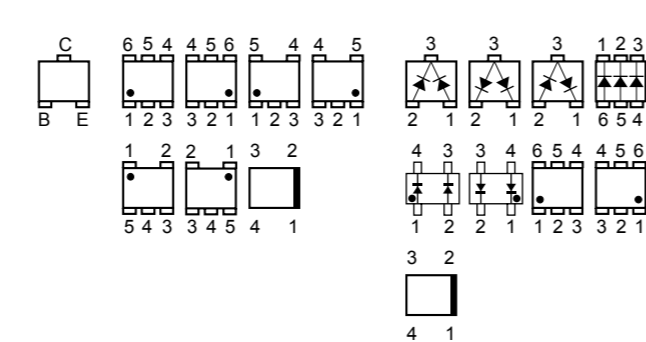
The components identified by mark Δ or dotted line with mark Δ are critical for safety.
Replace only with part number specified.

Les composants identifiés par une marque Δ sont critiques pour la sécurité.
Ne les remplacer que par une pièce portant le numéro spécifié.

For Printed Wiring Boards

- : Uses unleaded solder.
- : Circuit board
- : Flexible board
- Pattern from the side which enables seeing.
- : pattern of the rear side
(The other layers' patterns are not indicated)
- Through hole is omitted.
- There are a few cases that the part printed on diagram isn't mounted in this model.
- : panel designation

Chip parts.



回路図, プリント図共通ノート
(他に必要なノートは各セクションに記載しています)

回路図ノート

- ケミコン, タンタルを除くコンデンサで, 耐圧50V以下のものはその耐圧を省略。単位はすべて μF (pはpF)。
- チップ抵抗で指示のないものは, 1/10W以下。
 $\text{k}\Omega=1000\Omega$, $\text{M}\Omega=1000\text{k}\Omega$
- チップ部品交換時の注意
取り外した部品は再使用せず, 未使用の部品をご使用ください。
タンタルコンデンサのマイナス側は熱に弱いため注意してください。
- チップ部品には下記のように表示したものがああります。

例	C541	L452
	22U	10UH
	TA A	2520
	TA	A
	22U	10UH
	TA	A
	2520	

種類 外形寸法 (mm)
ケースサイズ

- 抵抗, コンデンサ, ICなど定数にXXがあるものは, 使用していない事を示しています。このため, 使用していない回路が記載されている事があります。
- ★印のある部品は, 機種などにより異なりますので機能別マウント一覧表を参照してください。
- 可変抵抗と半固定抵抗で, B特性の表示を省略。
- 信号名表記について, 下記のような場合があります。
XEDIT → $\overline{\text{EDIT}}$ PB/XREC → $\overline{\text{PB/REC}}$
- は不燃性抵抗。
- はヒューズ抵抗。
- はパネル表示名称。
- はB+ライン。
- はB-ライン。
- はBライン(+, -)の入出力方向を示す。
- は調整名称。

イメージ交換時の注意

- イメージを交換した場合は, カメラ部の全調整を行ってください。
- イメージは構造上, 静電気により破壊される恐れがあるため, MOS ICと同様に注意して取り扱ってください。
また, 受光部にはゴミの付着, および強い光がはいることのないように注意してください。

お願い
図面番号で部品を指定するときは基板名又はブロックを併せて指定してください。

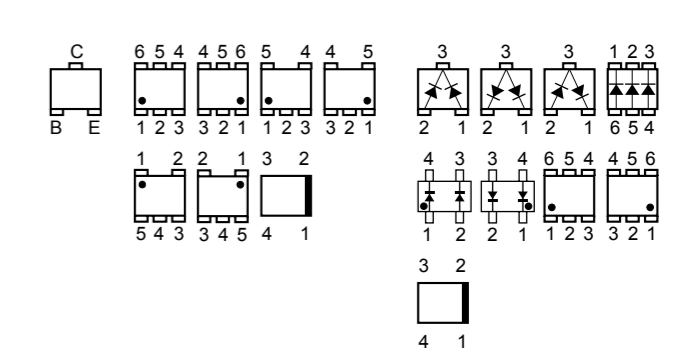
Δ 印の部品, または Δ 印付の点線で囲まれた部品は, 安全性を維持するために, 重要な部品です。
従って交換時は, 必ず指定の部品を使用してください。

- JAPANESE -

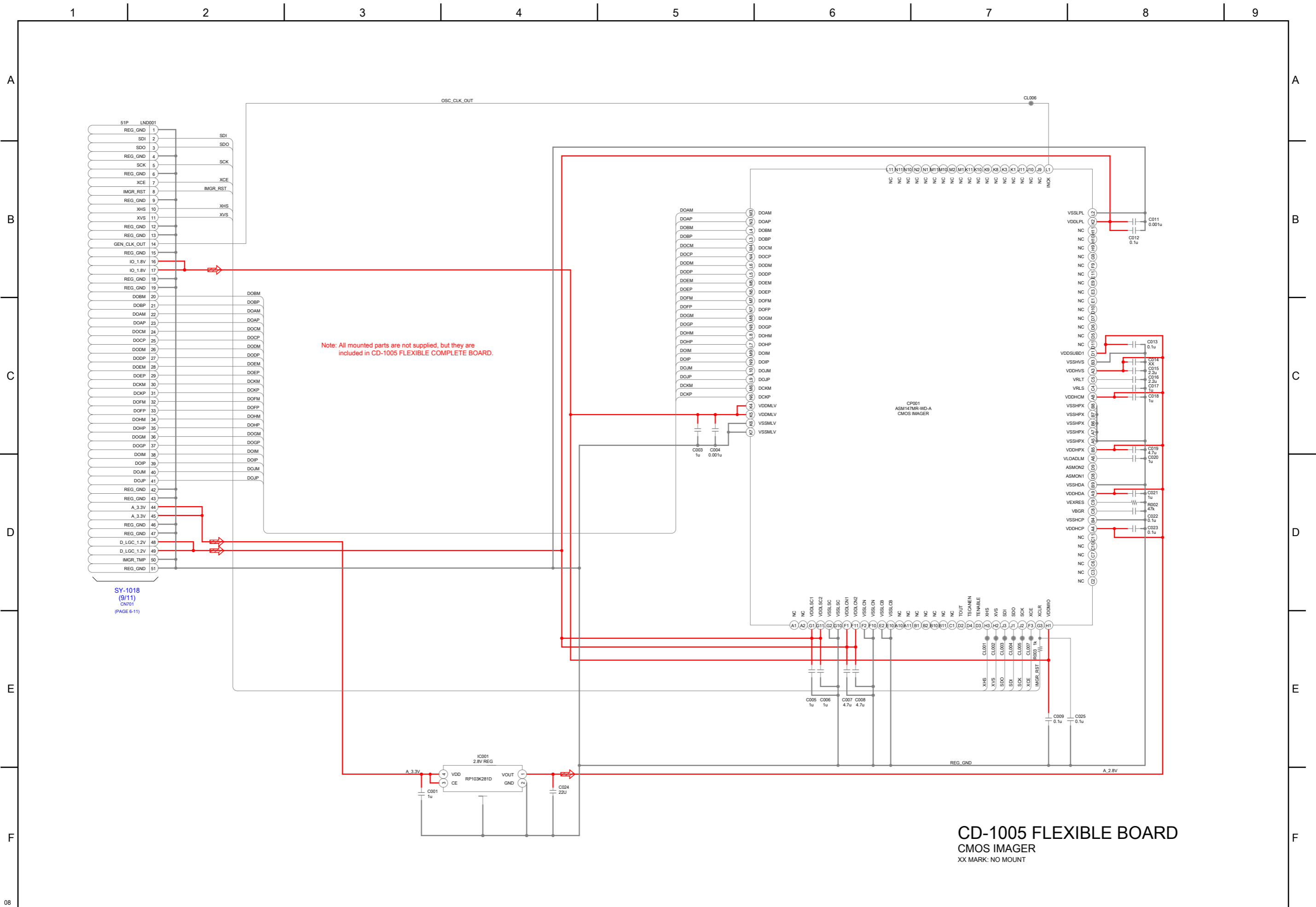
プリント図ノート

- : 無鉛半田を使用しています。
- : 基板
- : フレキシブル配線板
見ている面側のパターン。
- : 裏側のパターン
(他のパターンについては表示されていません)
- スルーホールは省略。
- プリント図には, 本機で使用していない部品が記載されている場合があります。
- はパネル表示名称。

Chip parts.



6-1. SCHEMATIC DIAGRAMS



1 2 3 4 5 6 7 8 9

A

A

B

B

C

C

D

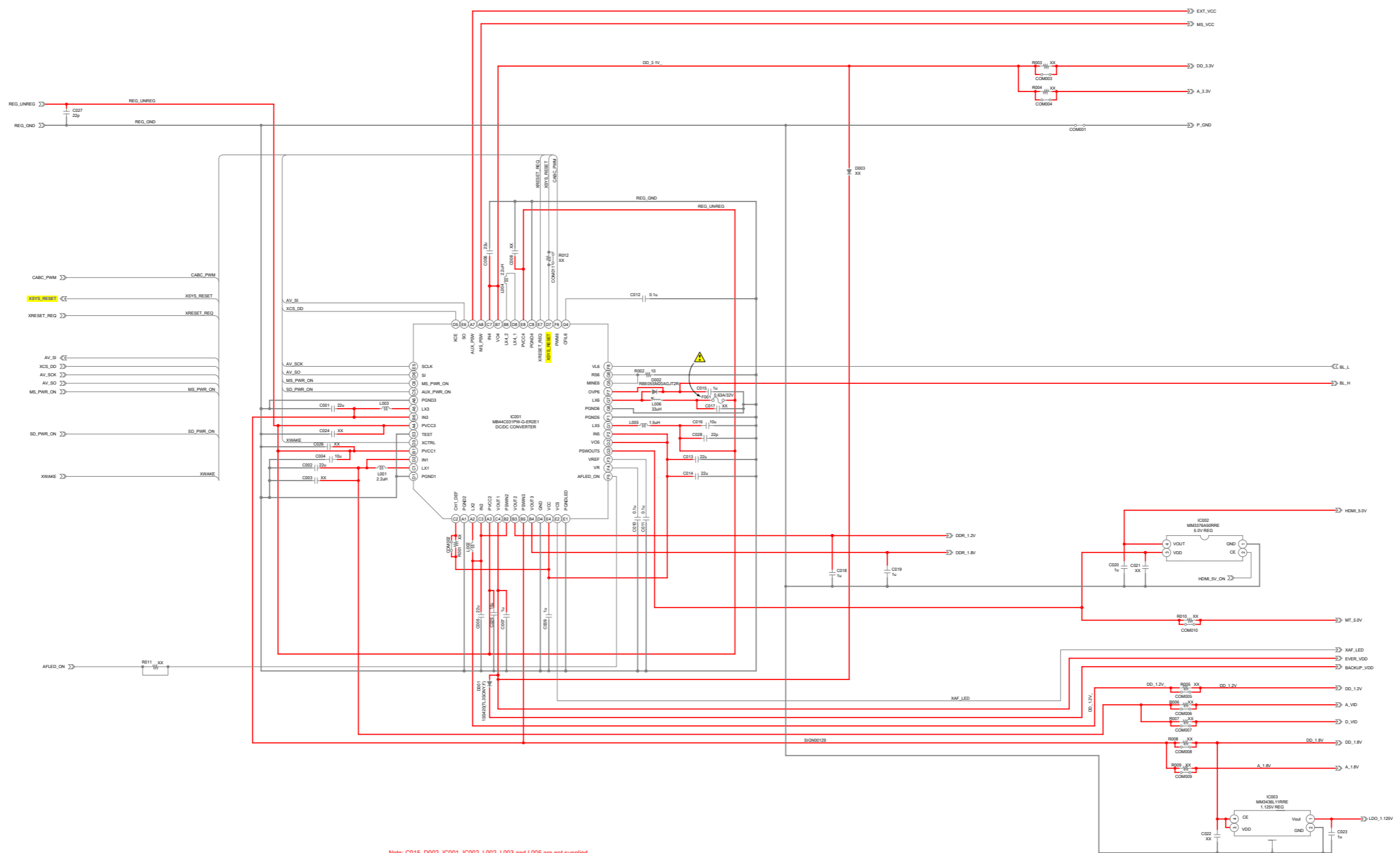
D

E

E

F

F



Note: C015, D002, IC001, IC002, L002, L003 and L005 are not supplied,
but they are included in SY-1018 COMPLETE BOARD (SERVICE).

SY-1018 BOARD (1/11)
DC/DC CONVERTER
XX MARK: NO MOUNT

1 2 3 4 5 6 7 8 9

A

A

B

B

C

C

D

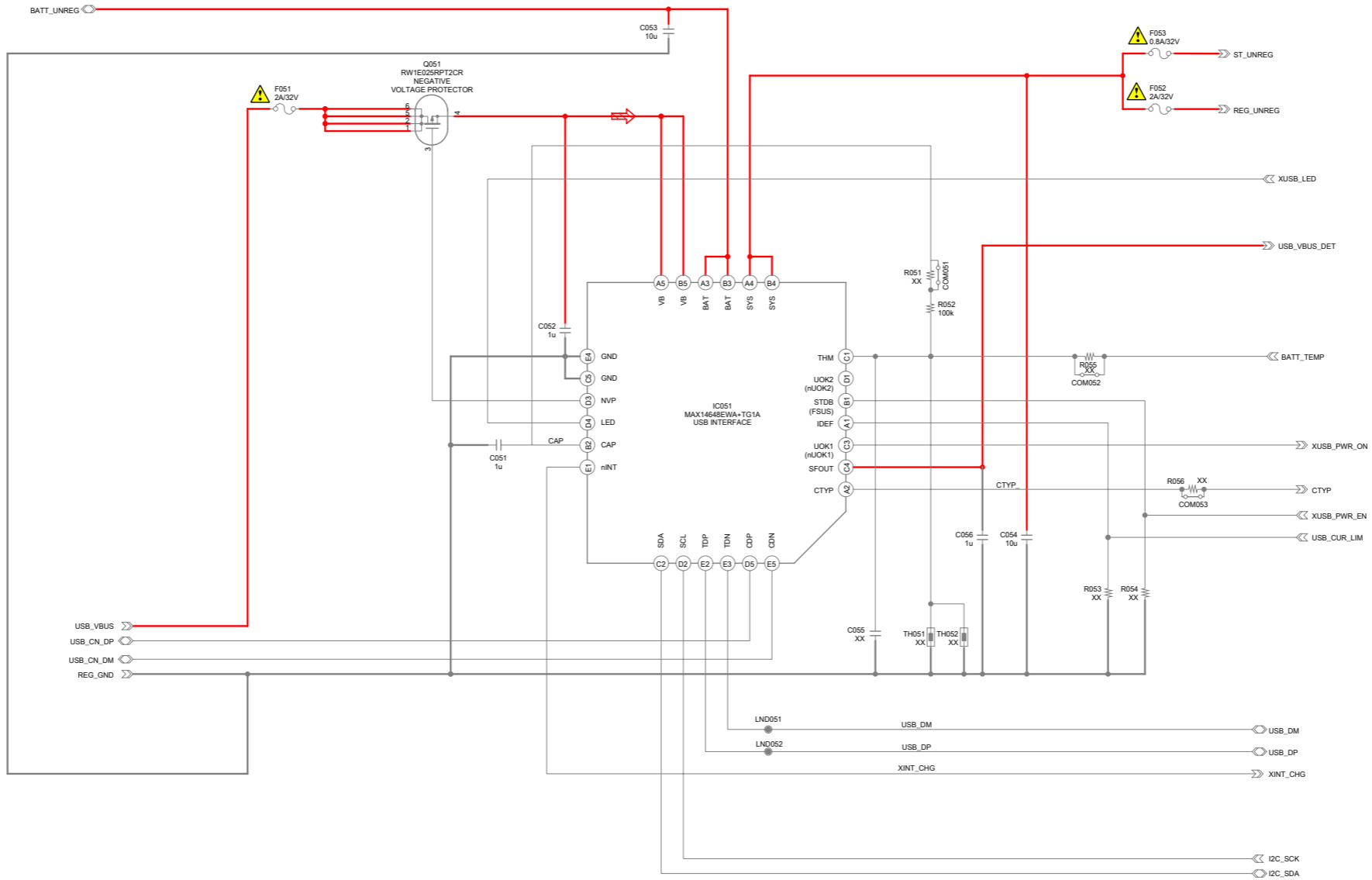
D

E

E

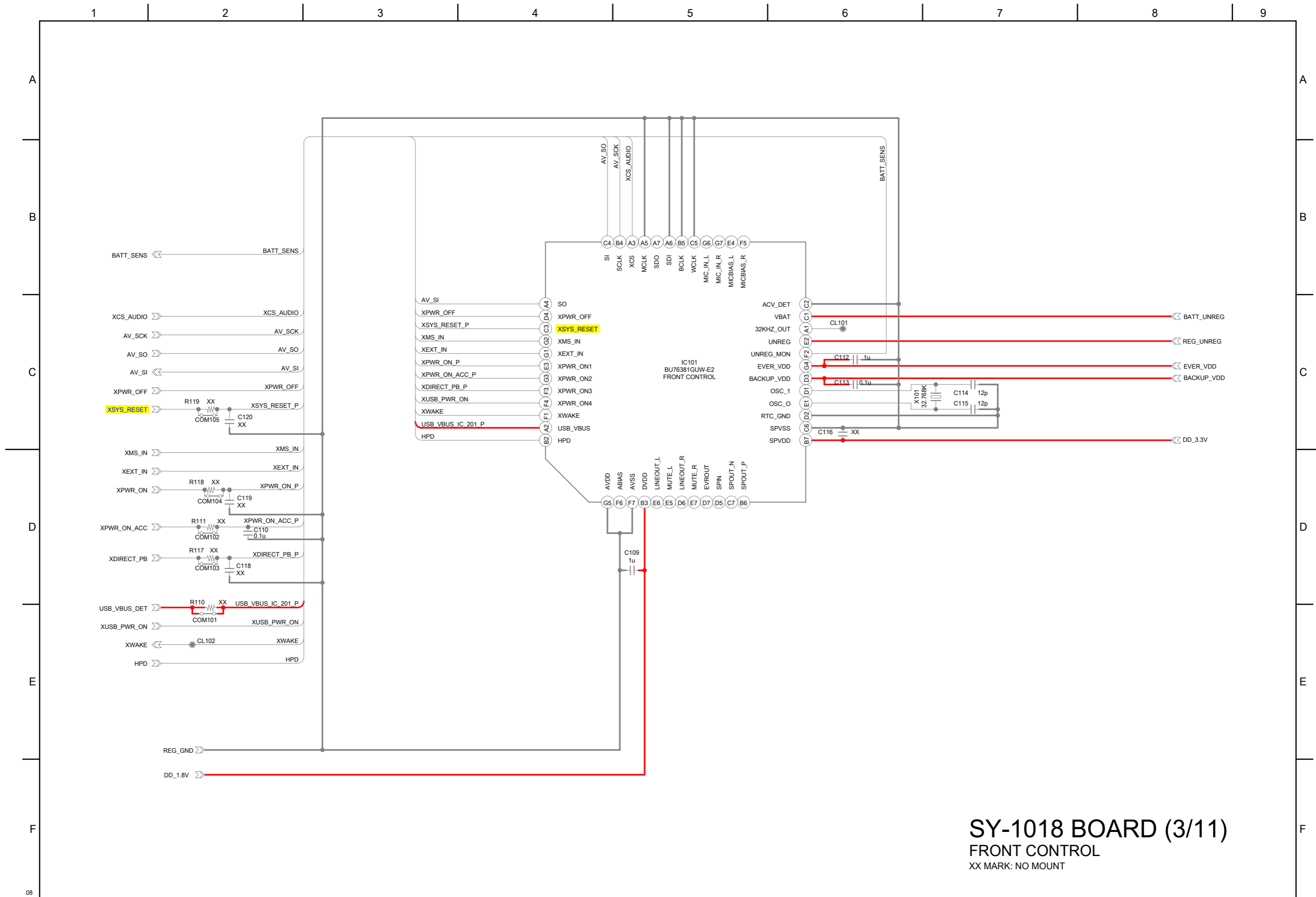
F

F



Note: IC051 is not supplied, but this is included in SY-1018 COMPLETE BOARD (SERVICE).

SY-1018 BOARD (2/11)
USB INTERFACE
XX MARK: NO MOUNT

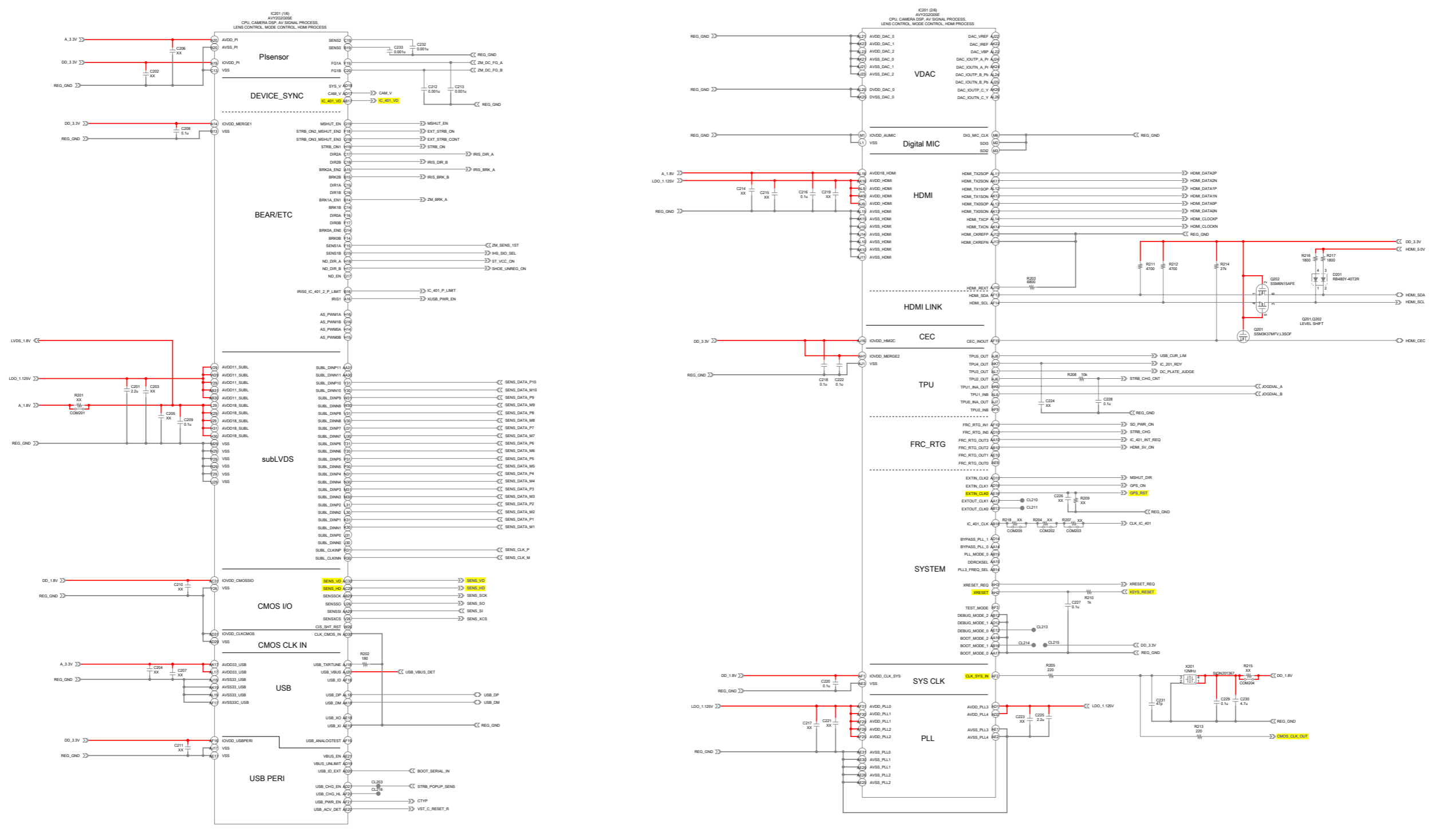


SY-1018 BOARD (3/11)
FRONT CONTROL
 XX MARK: NO MOUNT

1 2 3 4 5 6 7 8 9

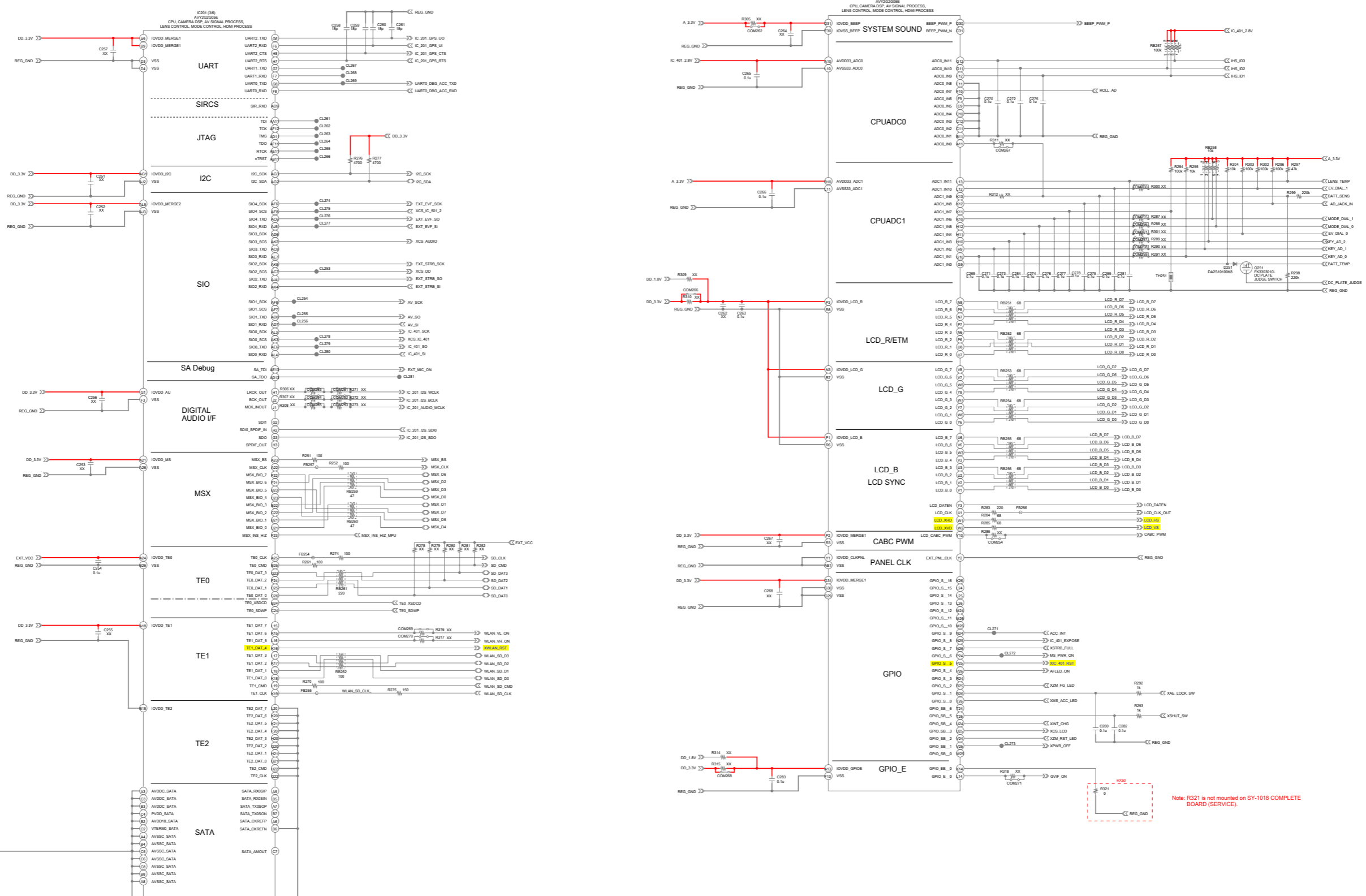
A
B
C
D
E
F

Note: C212, C213, C225, C232, C233 and IC201 are not supplied, but they are included in SY-1018 COMPLETE BOARD (SERVICE).



SY-1018 BOARD (4/11)
CPU, CAMERA DSP, AV SIGNAL PROCESS,
LENS CONTROL, MODE CONTROL, HDMI PROCESS (1/3)
XX MARK: NO MOUNT

Note: IC201 is not supplied, but this is included in SY-1018 COMPLETE BOARD (SERVICE).



Note: R321 is not mounted on SY-1018 COMPLETE BOARD (SERVICE).

SY-1018 BOARD (5/11)
CPU, CAMERA DSP, AV SIGNAL PROCESS,
LENS CONTROL, MODE CONTROL, HDMI PROCESS (2/3)
XX MARK: NO MOUNT

1 2 3 4 5 6 7 8 9

A

A

B

B

C

C

D

D

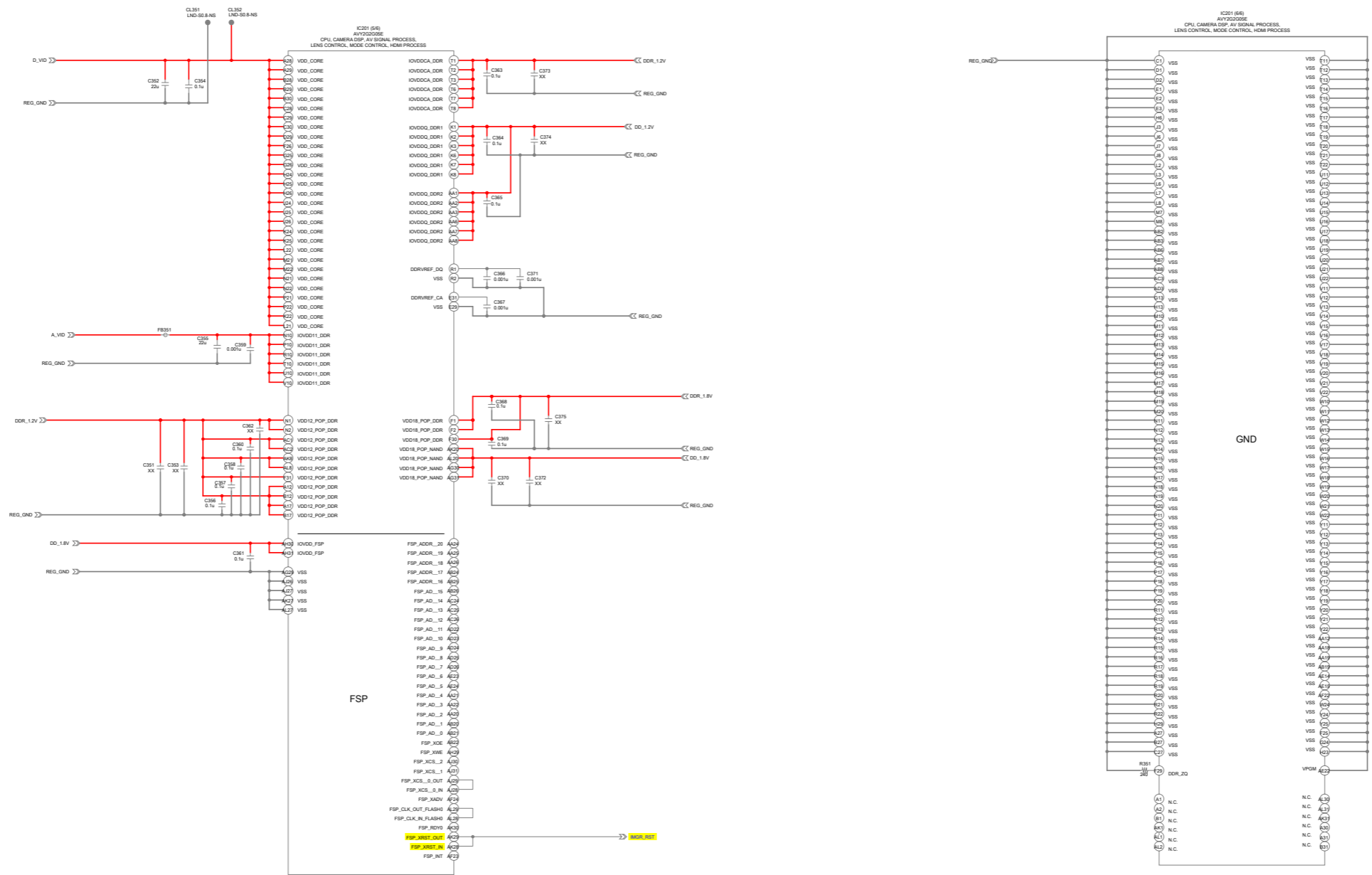
E

E

F

F

Note: C359, C366, C367, C371 and IC201 are not supplied, but they are included in SY-1018 COMPLETE BOARD (SERVICE).



SY-1018 BOARD (6/11)
CPU, CAMERA DSP, AV SIGNAL PROCESS,
LENS CONTROL, MODE CONTROL, HDMI PROCESS (3/3)
XX MARK: NO MOUNT

1 2 3 4 5 6 7 8 9

A

A

B

B

C

C

D

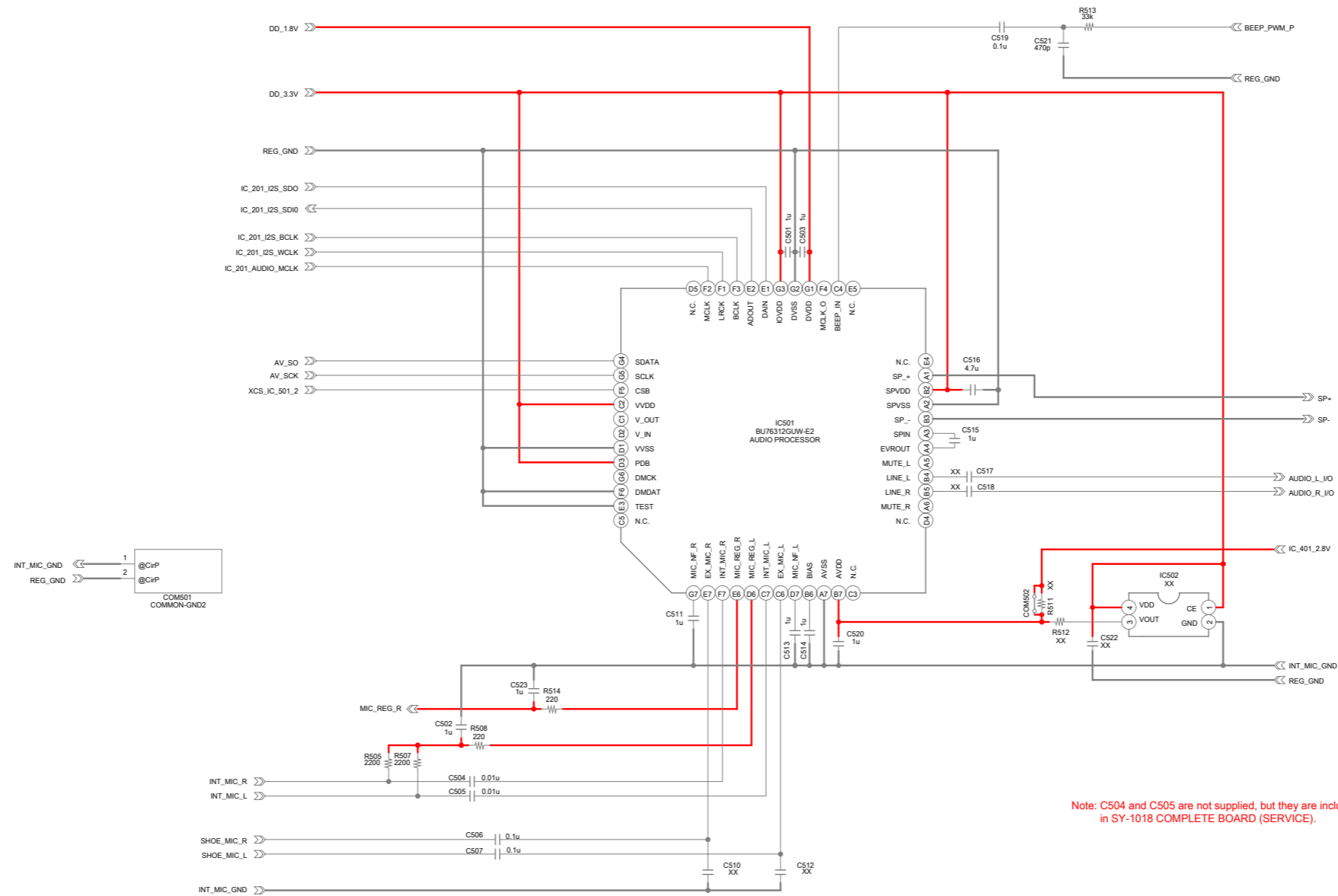
D

E

E

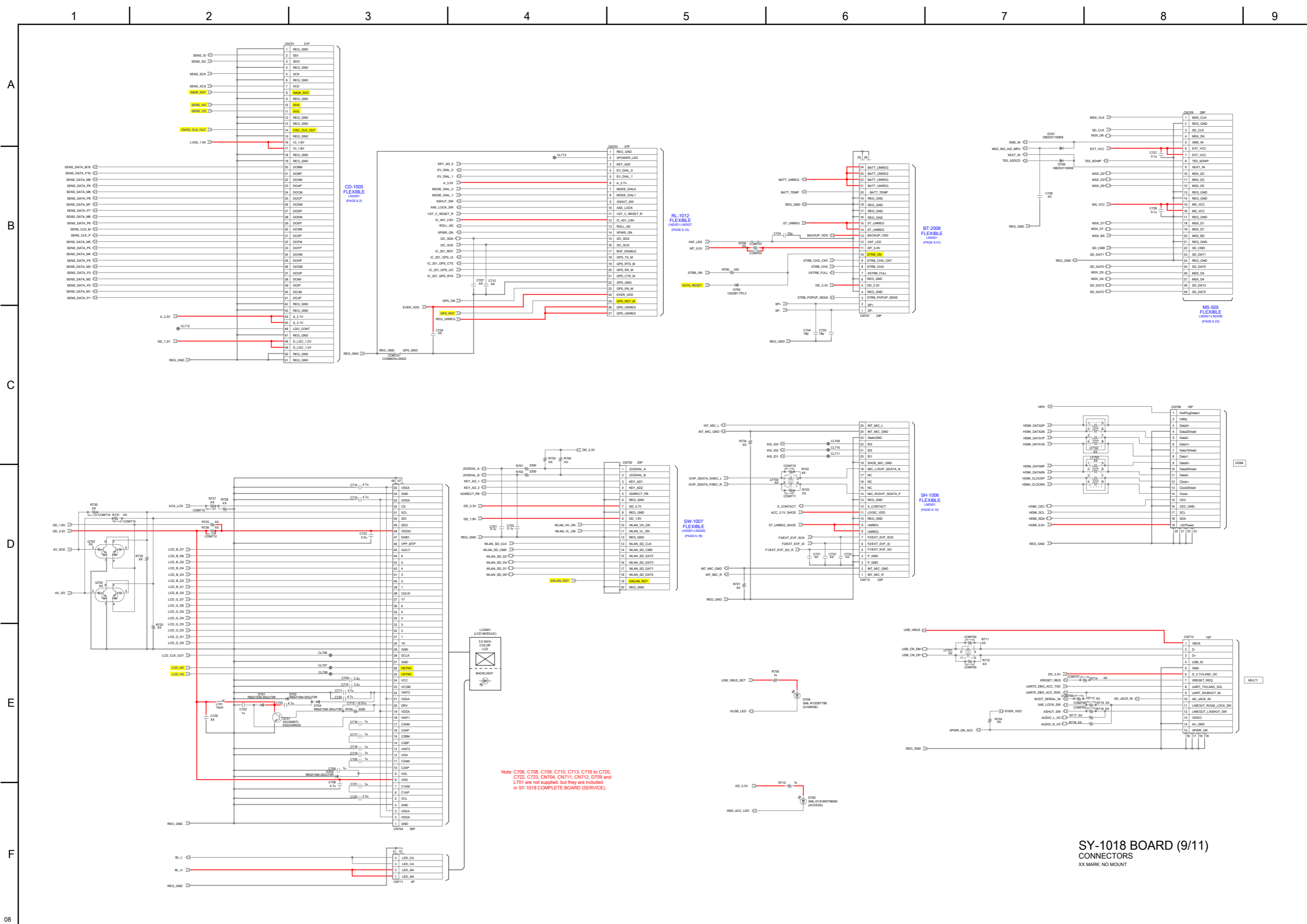
F

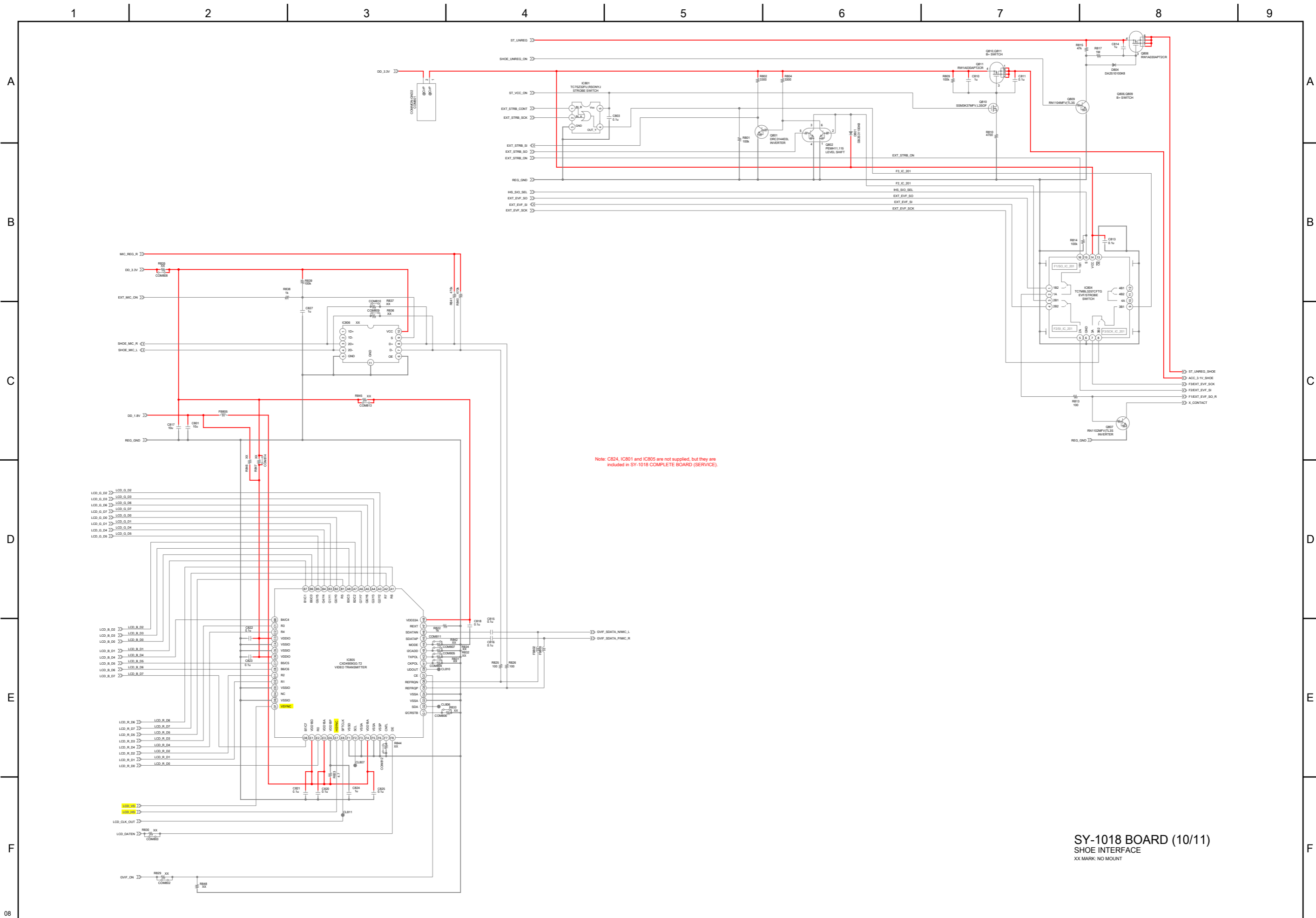
F

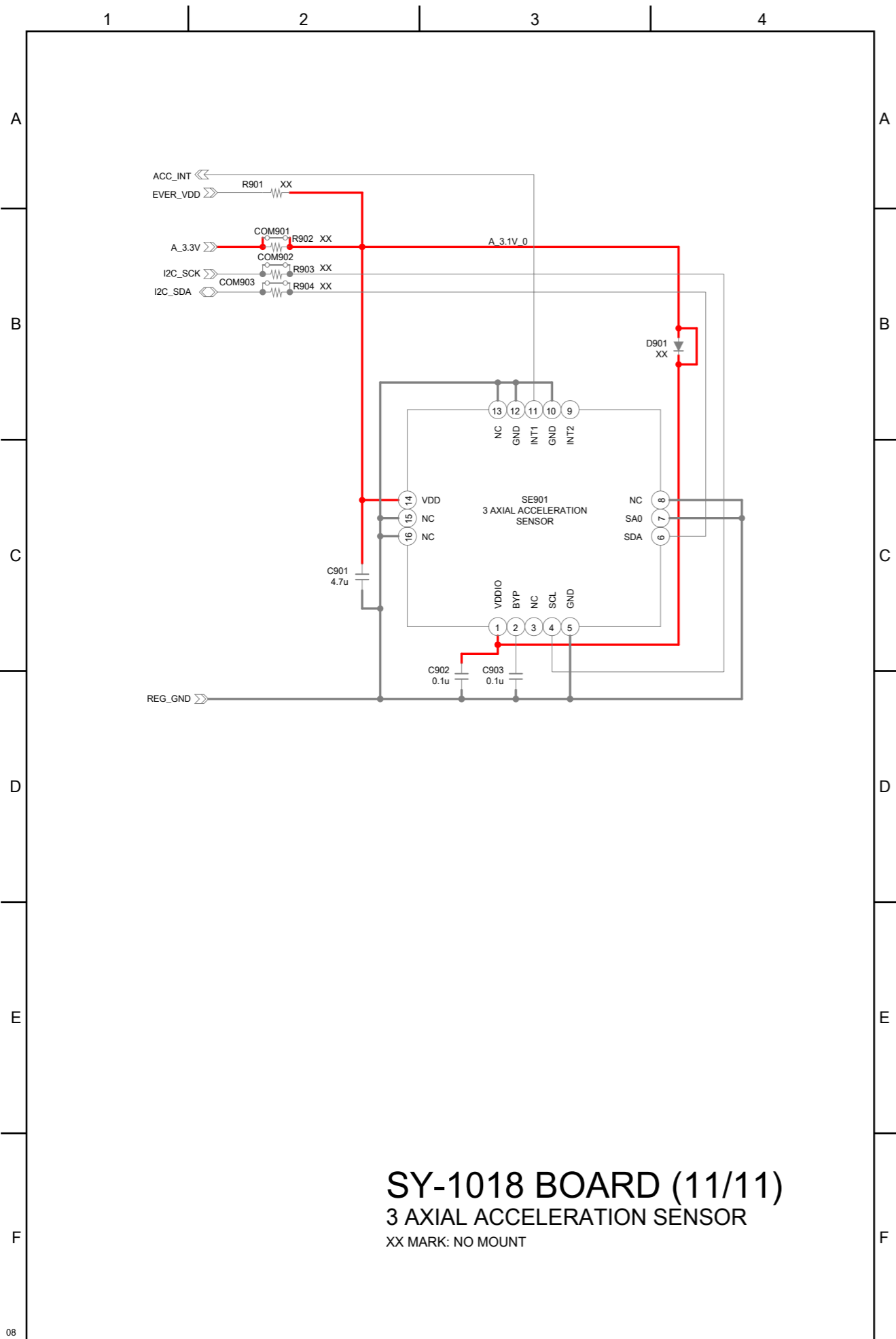


Note: C504 and C505 are not supplied, but they are included in SY-1018 COMPLETE BOARD (SERVICE).

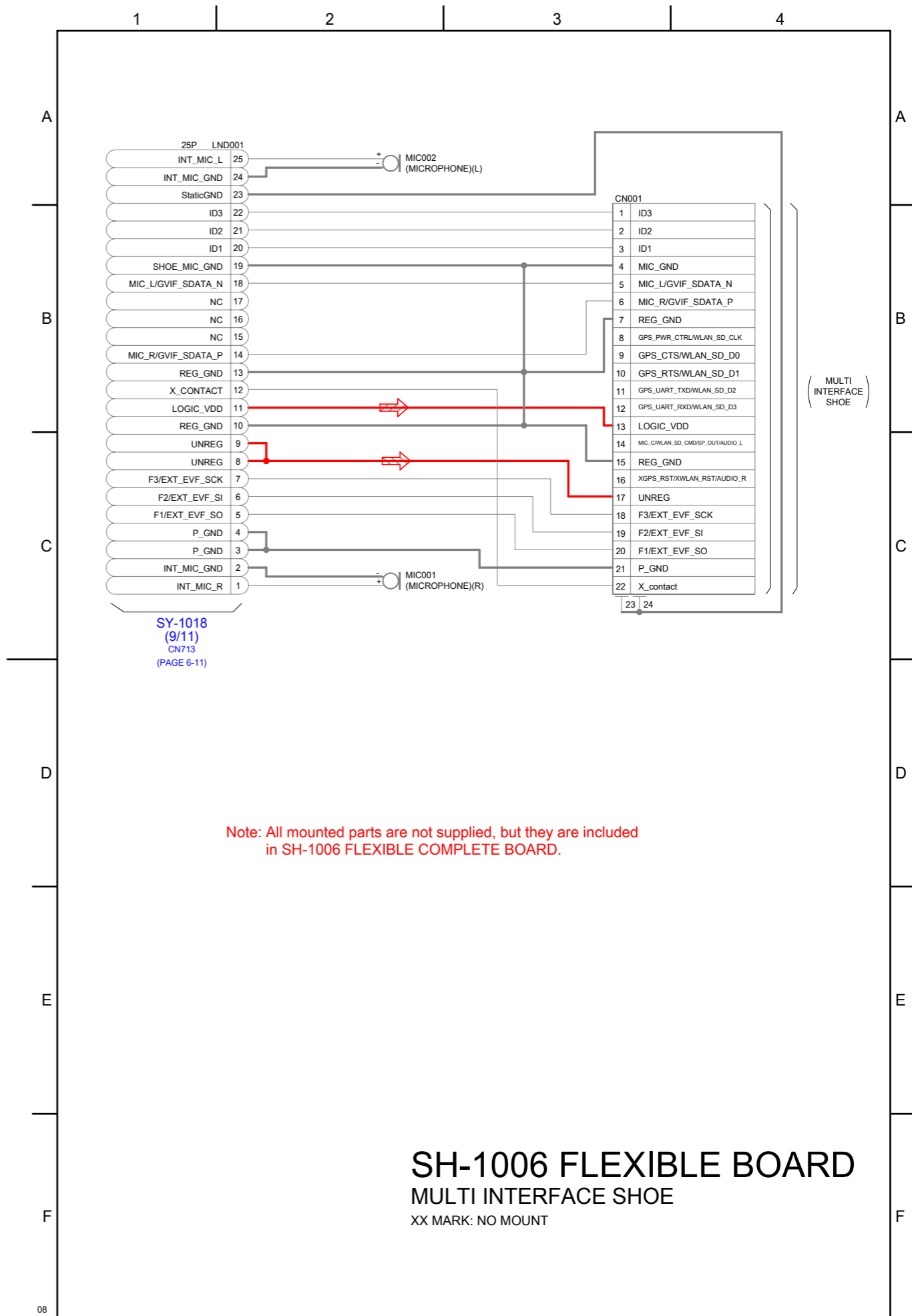
SY-1018 BOARD (8/11) AUDIO PROCESSOR XX MARK: NO MOUNT







SY-1018 BOARD (11/11)
3 AXIAL ACCELERATION SENSOR
XX MARK: NO MOUNT



Note: All mounted parts are not supplied, but they are included in SH-1006 FLEXIBLE COMPLETE BOARD.

SH-1006 FLEXIBLE BOARD
MULTI INTERFACE SHOE
XX MARK: NO MOUNT

1 2 3 4 5 6 7 8 9

A

A

B

B

C

C

D

D

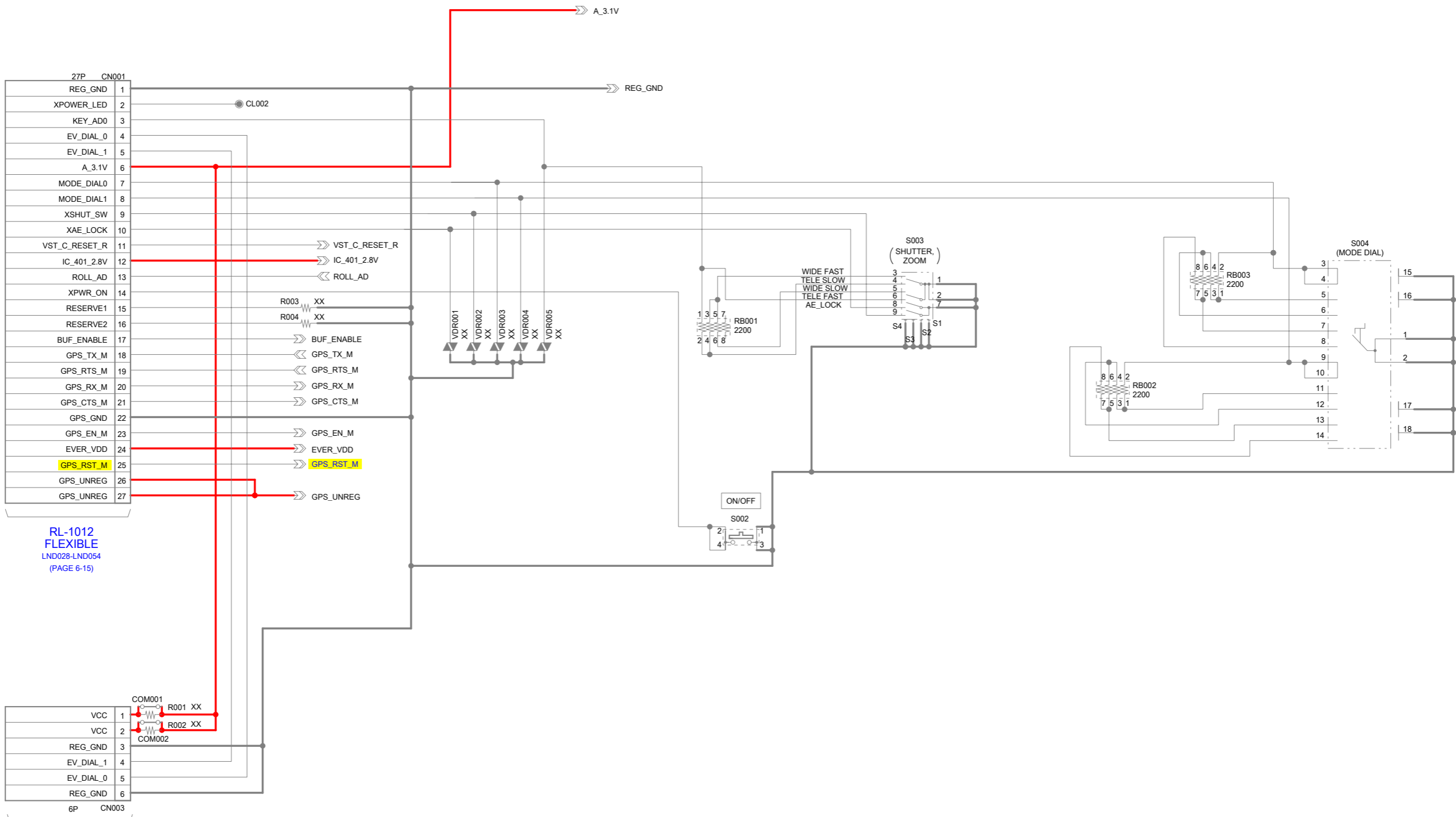
E

E

F

F

Note: S003 is not supplied, but this is included in RL-1011 COMPLETE BOARD (SERVICE).

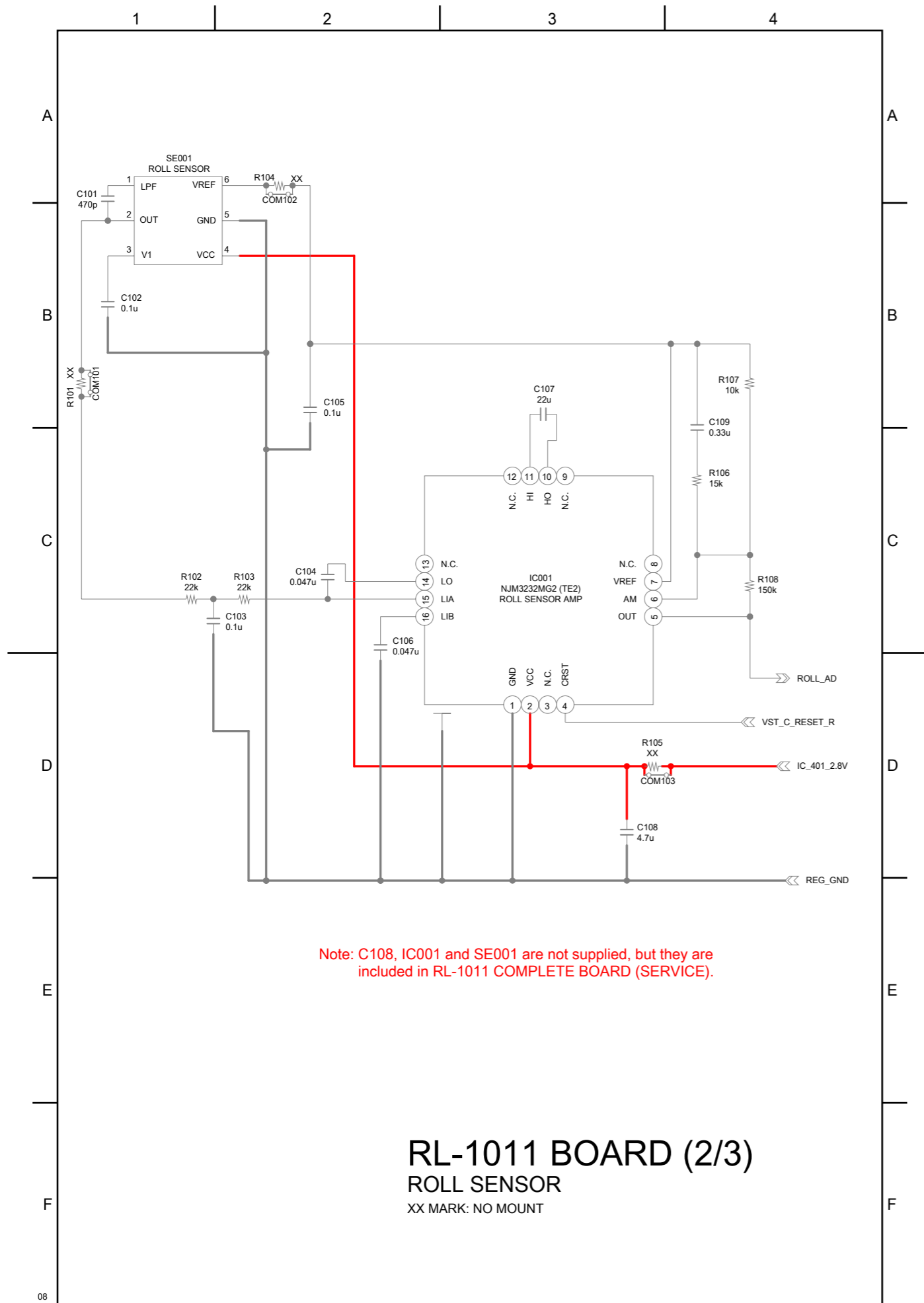


RL-1012 FLEXIBLE LND028-LND054 (PAGE 6-15)

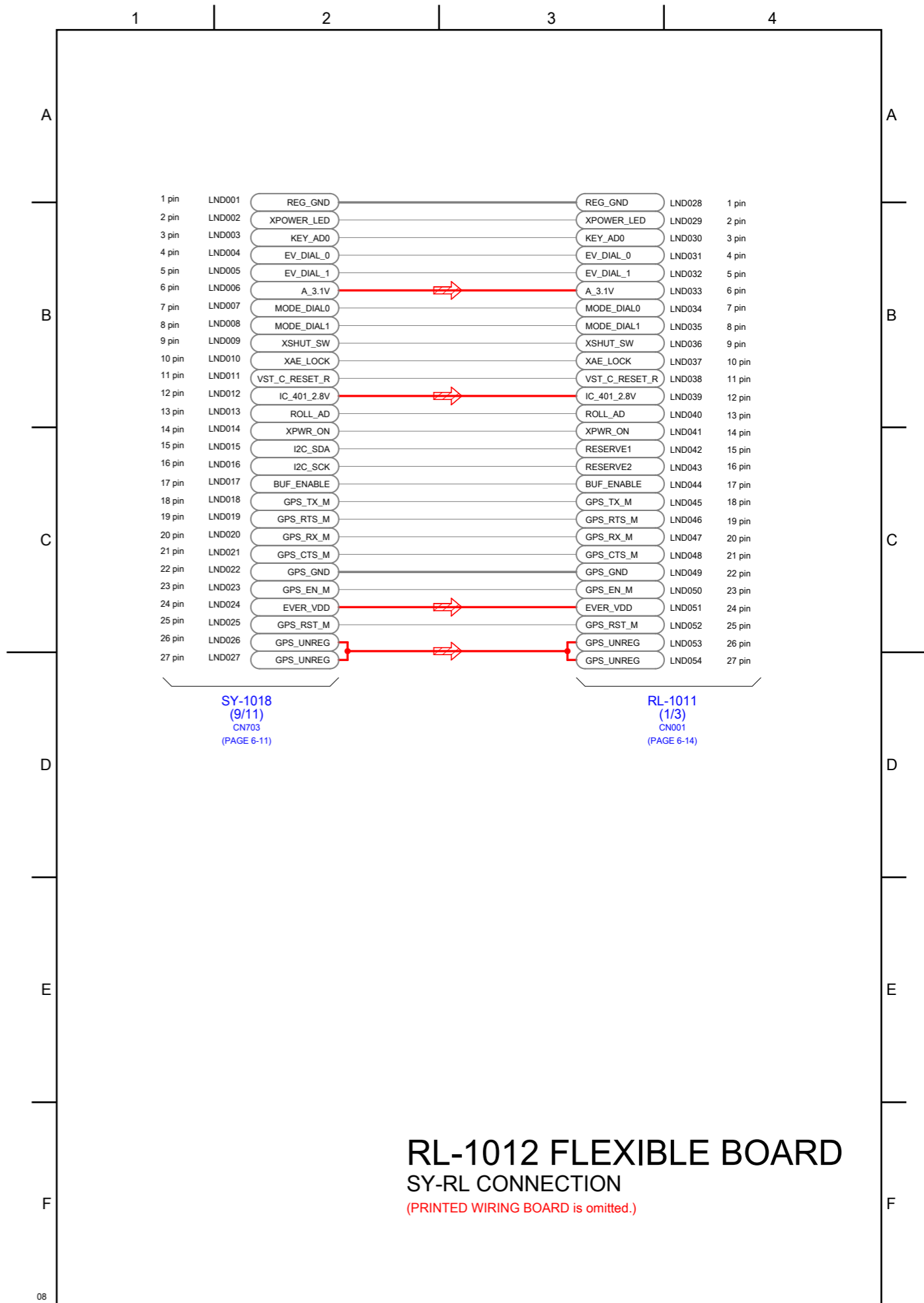
CONTROL SWITCH BLOCK (SW63470)

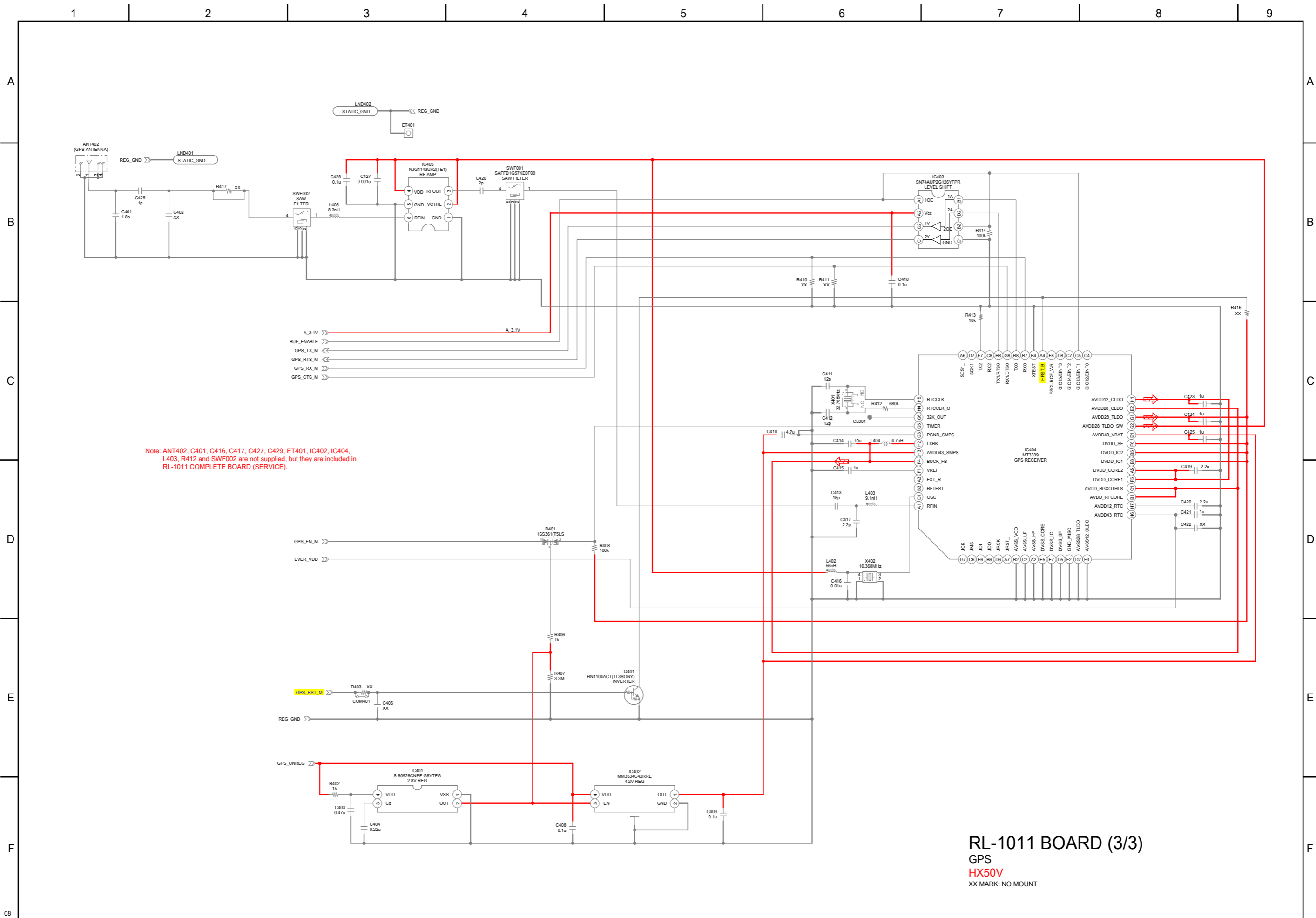
Note: CONTROL SWITCH BLOCK (SW63470) is not included in RL-1011 COMPLETE BOARD (SERVICE).

RL-1011 BOARD (1/3)
MODE DIAL
XX MARK: NO MOUNT



Note: C108, IC001 and SE001 are not supplied, but they are included in RL-1011 COMPLETE BOARD (SERVICE).



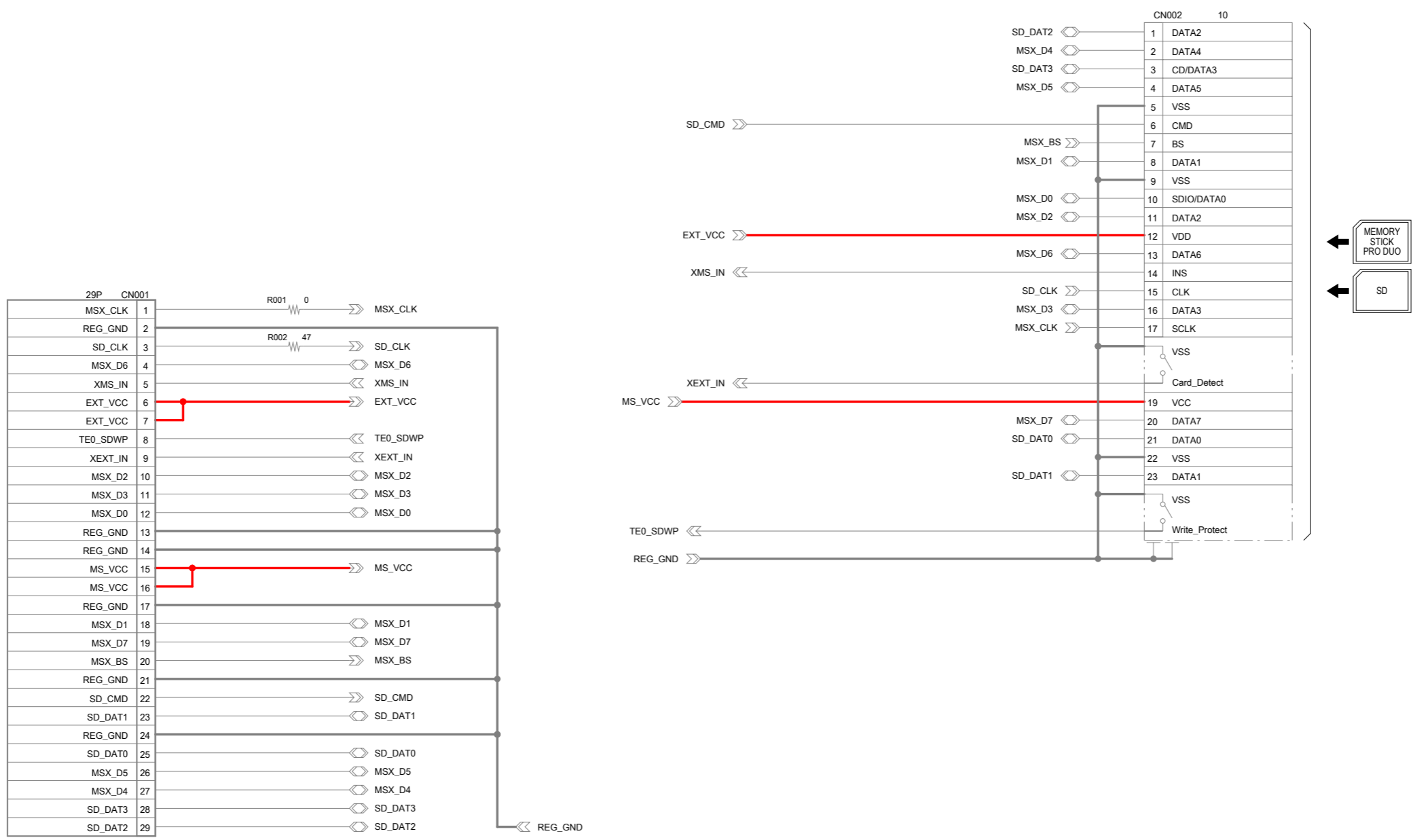


RL-1011 BOARD (3/3)
 GPS
 HX50V
 XX MARK: NO MOUNT

1 2 3 4 5 6 7 8 9

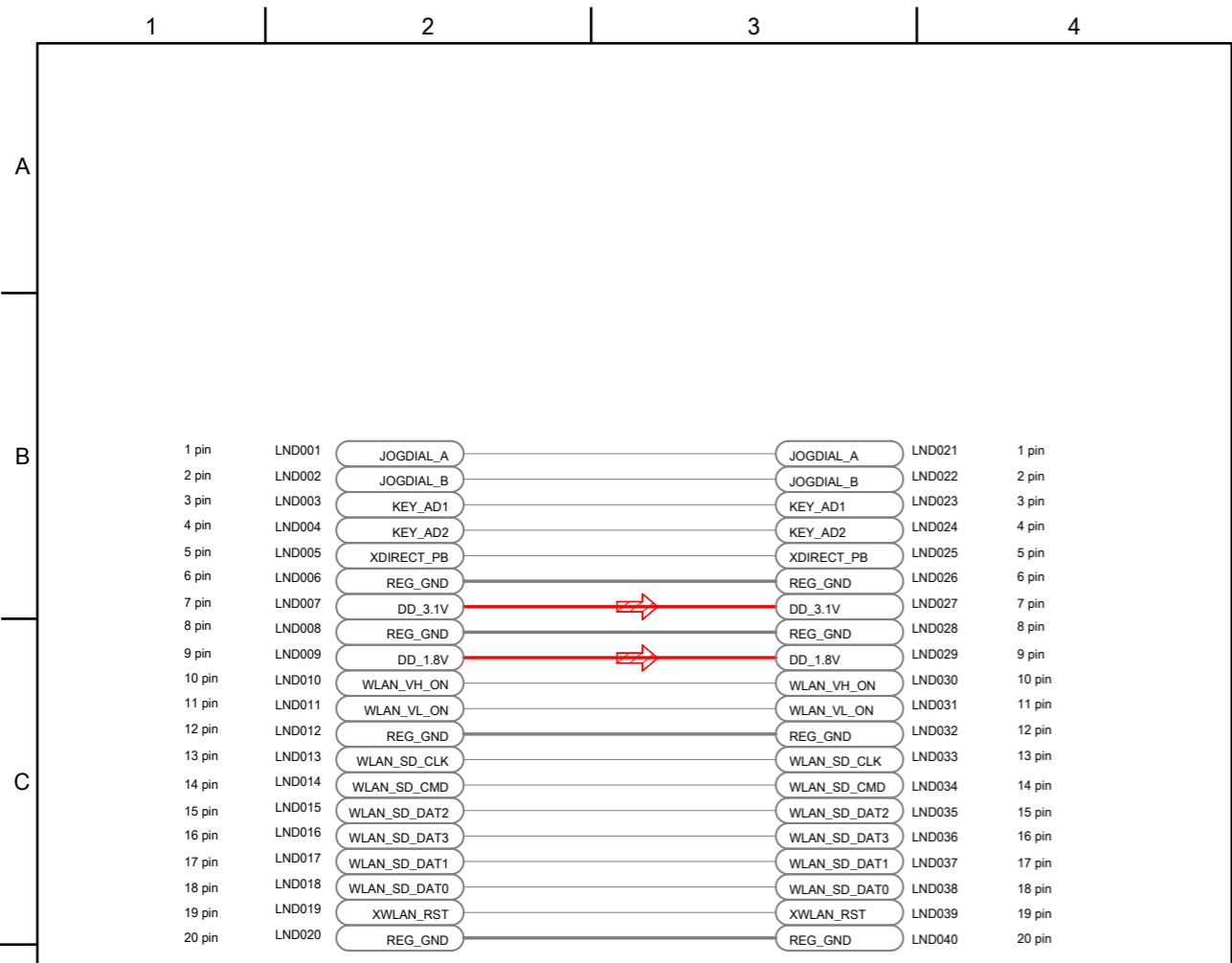
A
B
C
D
E
F

A
B
C
D
E
F



MS-505
FLEXIBLE
LND030-LND058
(PAGE 6-23)

MS-1013 BOARD
MEMORY CARD CONNECTOR
XX MARK: NO MOUNT

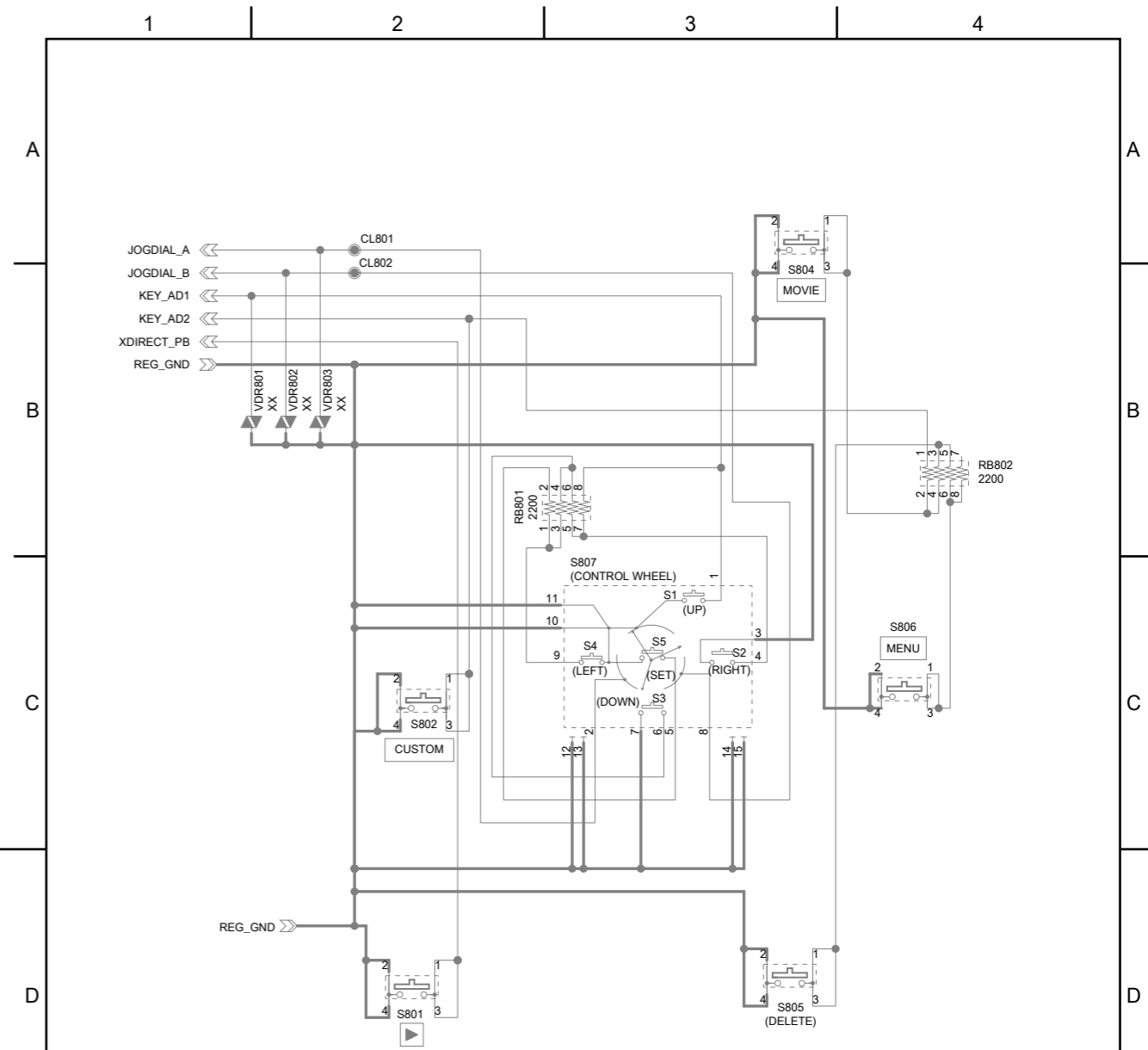


SY-1018
(9/11)
CN702
(PAGE 6-11)

SW-1006
(2/2)
CN901
(PAGE 6-19)

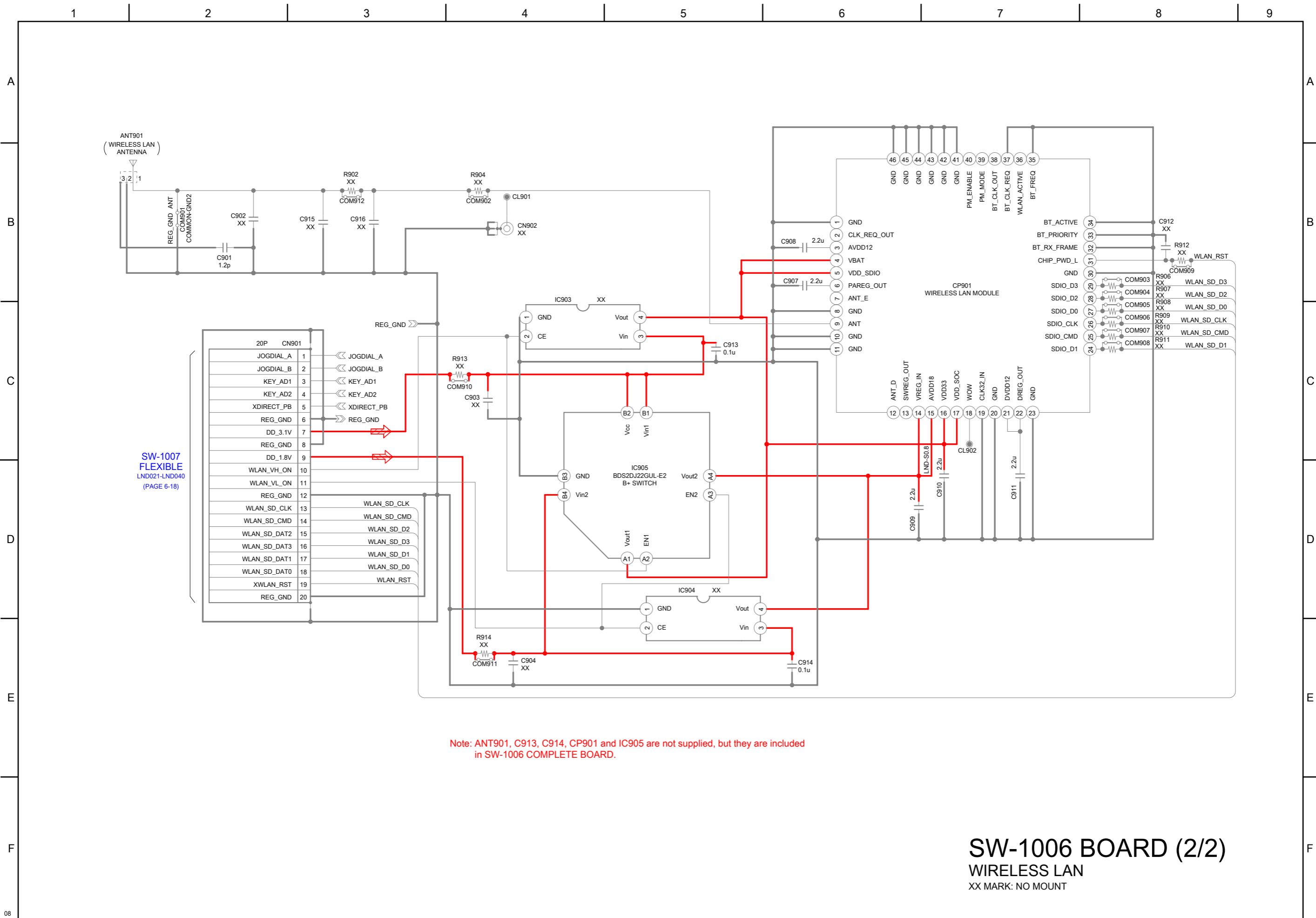
SW-1007 FLEXIBLE BOARD

SY-SW CONNECTION
(PRINTED WIRING BOARD is omitted.)



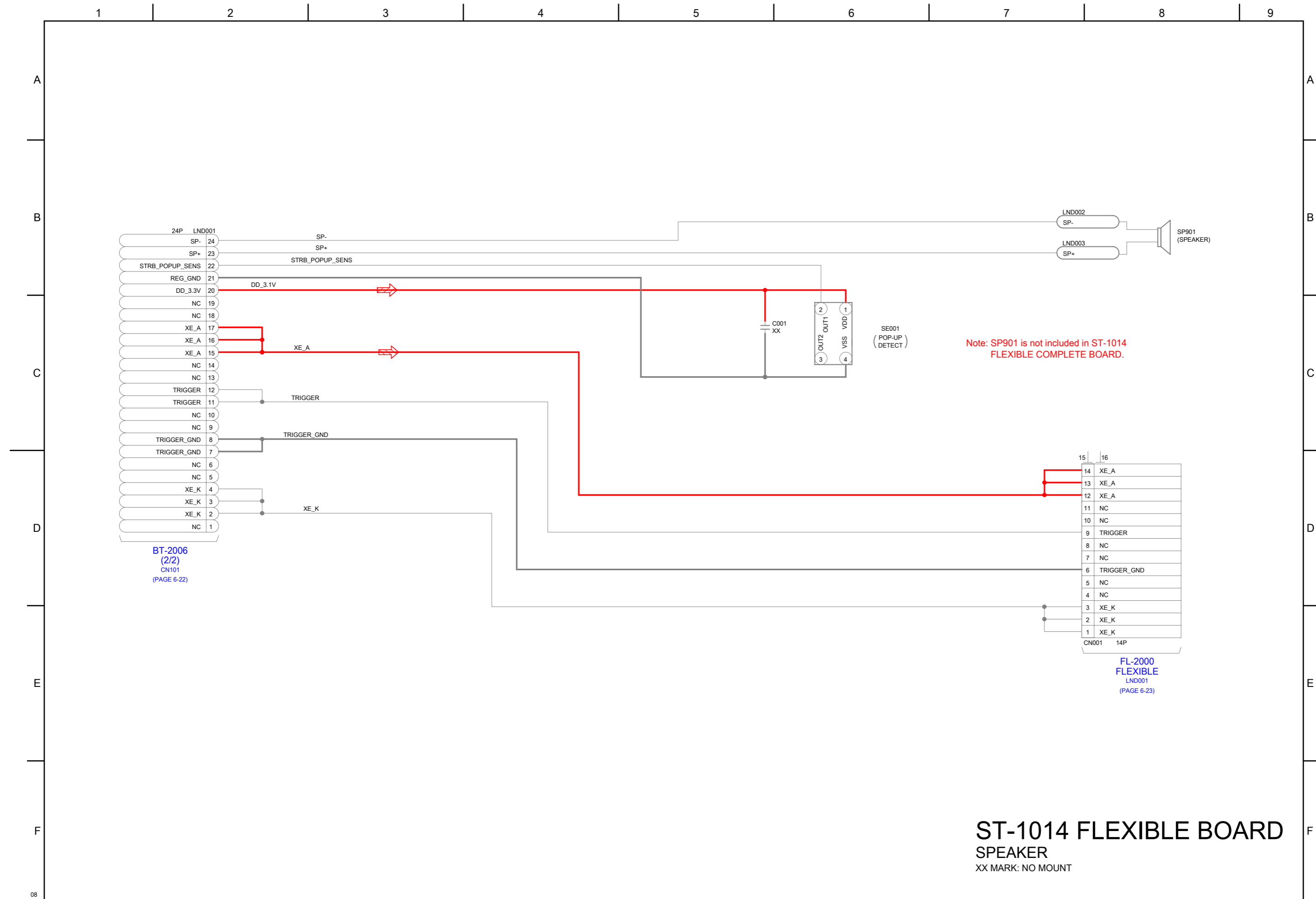
SW-1006 BOARD (1/2)

CONTROL SWITCHES
XX MARK: NO MOUNT



Note: ANT901, C913, C914, CP901 and IC905 are not supplied, but they are included in SW-1006 COMPLETE BOARD.

SW-1006 BOARD (2/2)
WIRELESS LAN
 XX MARK: NO MOUNT



ST-1014 FLEXIBLE BOARD
SPEAKER
XX MARK: NO MOUNT

1 2 3 4 5 6 7 8 9

A

B

C

D

E

F

A

B

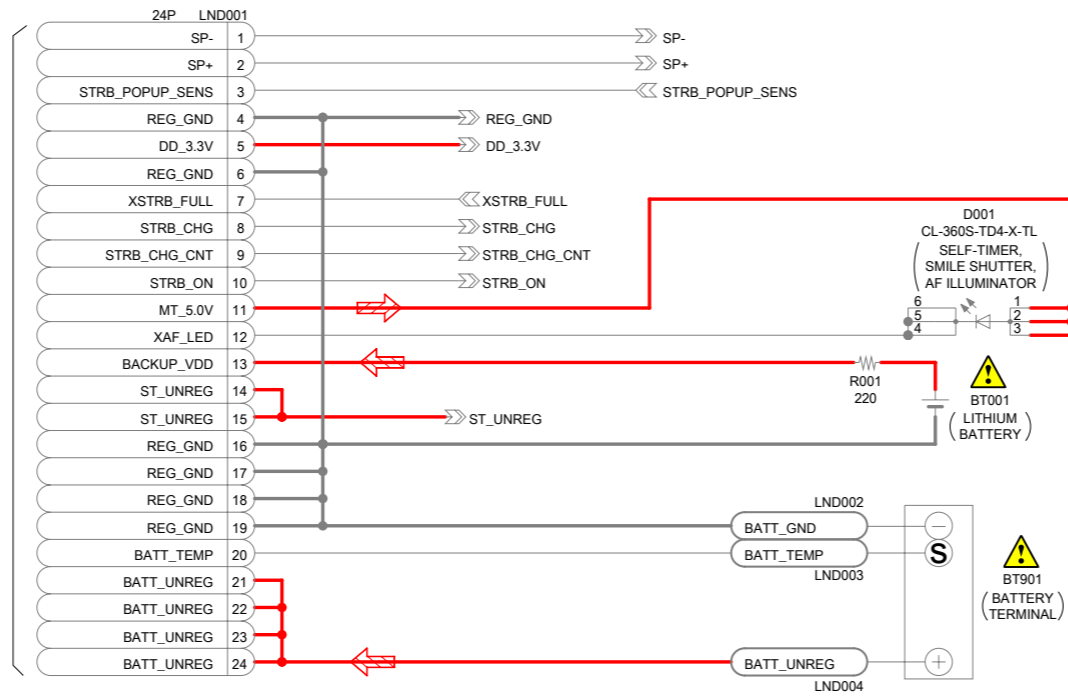
C

D

E

F

SY-1018
(9/11)
CN707
(PAGE 6-11)



Note: BT001 and BT901 are not included in
BT-2006 FLEXIBLE COMPLETE BOARD.

BT-2006 FLEXIBLE BOARD (1/2)
BATTERY TERMINAL
XX MARK: NO MOUNT

1 2 3 4 5 6 7 8 9

A

B

C

D

E

F

A

B

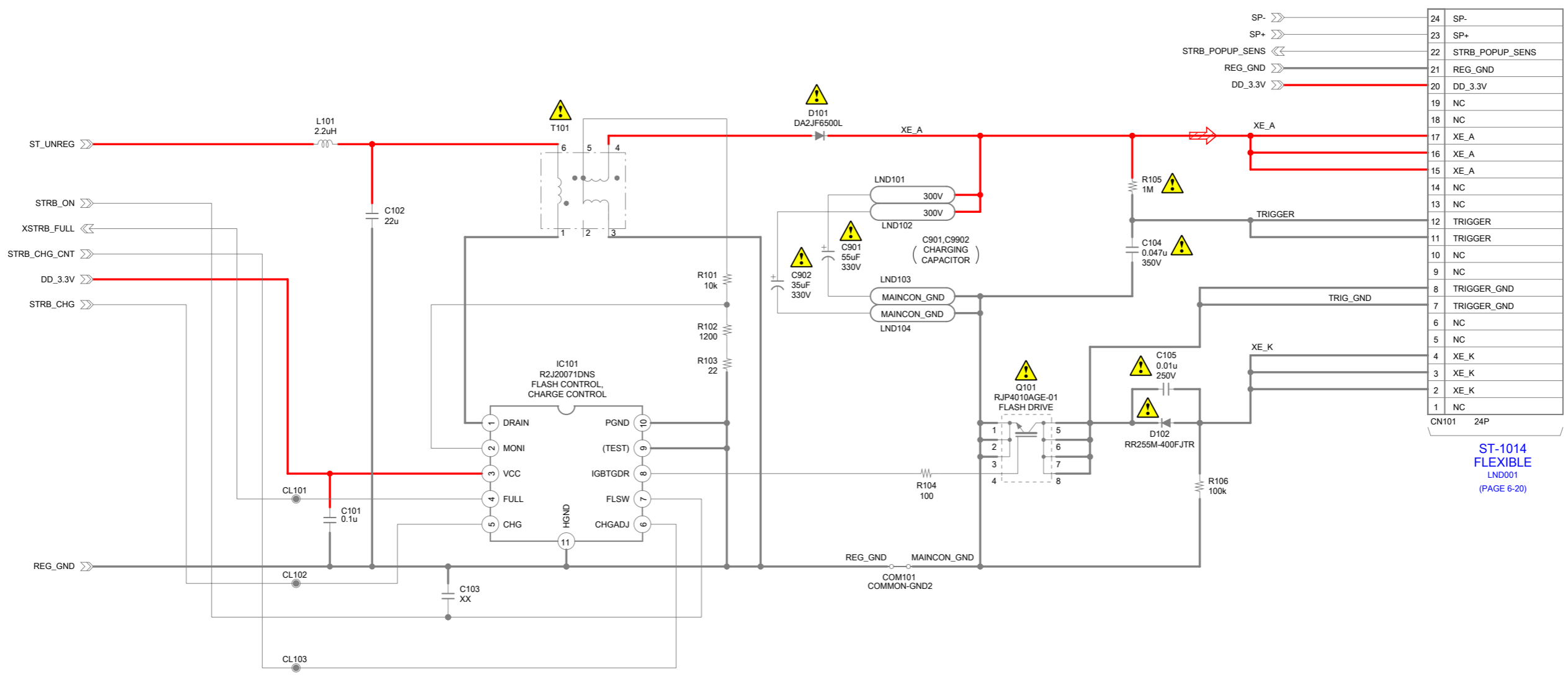
C

D

E

F

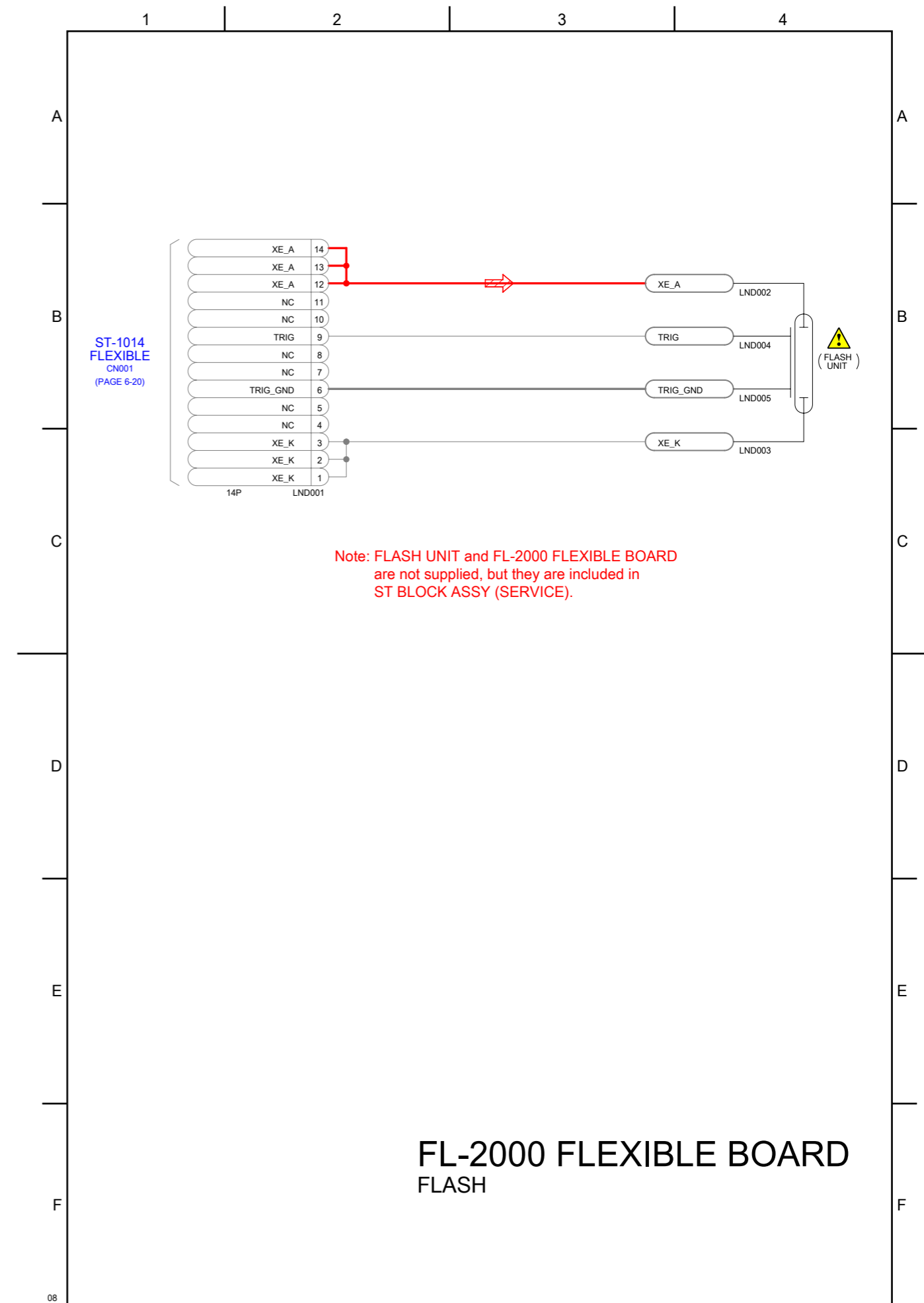
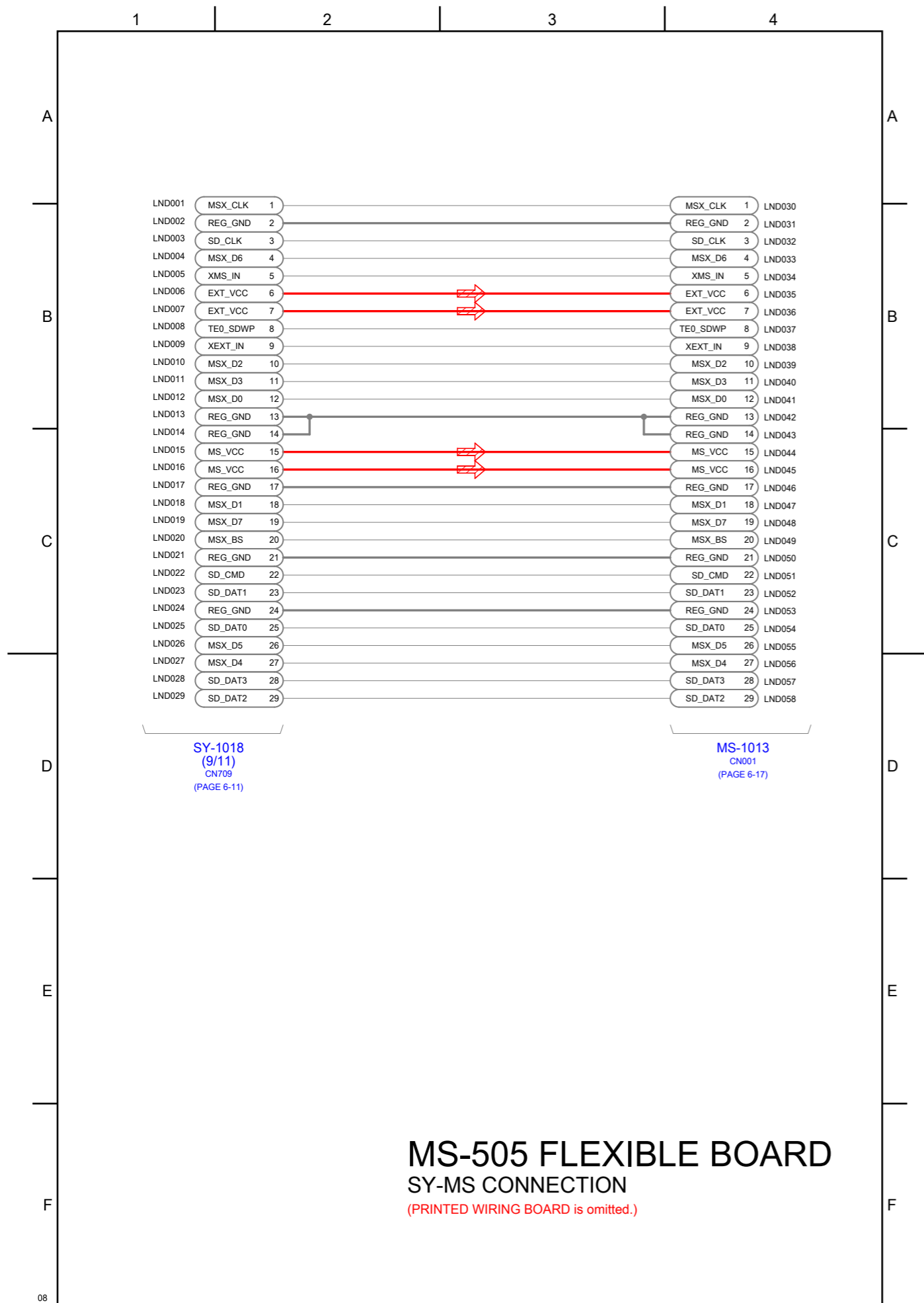
Note: C901 and C902 are not included
in BT-2006 FLEXIBLE COMPLETE BOARD.



SP-	24	SP-
SP+	23	SP+
STRB_POPUP_SENS	22	STRB_POPUP_SENS
REG_GND	21	REG_GND
DD_3.3V	20	DD_3.3V
	19	NC
	18	NC
	17	XE_A
	16	XE_A
	15	XE_A
	14	NC
	13	NC
	12	TRIGGER
	11	TRIGGER
	10	NC
	9	NC
	8	TRIGGER_GND
	7	TRIGGER_GND
	6	NC
	5	NC
	4	XE_K
	3	XE_K
	2	XE_K
	1	NC
CN101	24P	

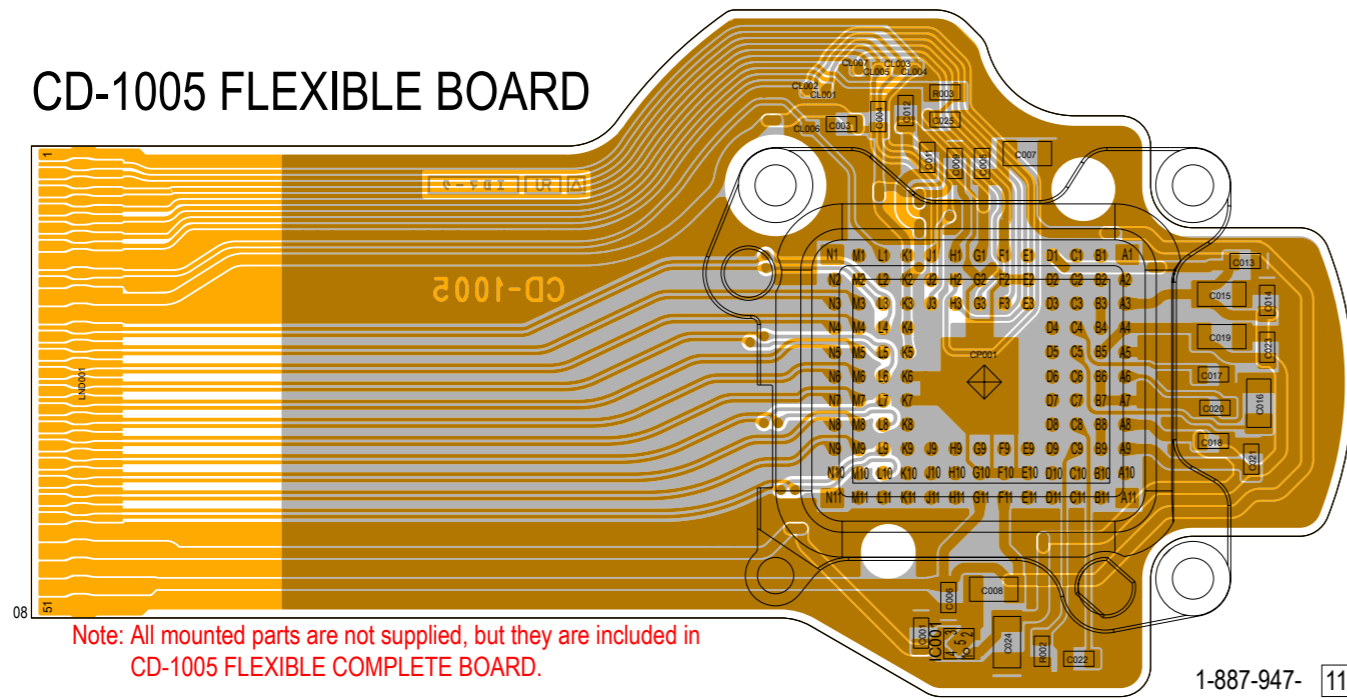
ST-1014
FLEXIBLE
LND001
(PAGE 6-20)

BT-2006 FLEXIBLE BOARD (2/2)
FLASH DRIVE
XX MARK: NO MOUNT



6-2. PRINTED WIRING BOARDS

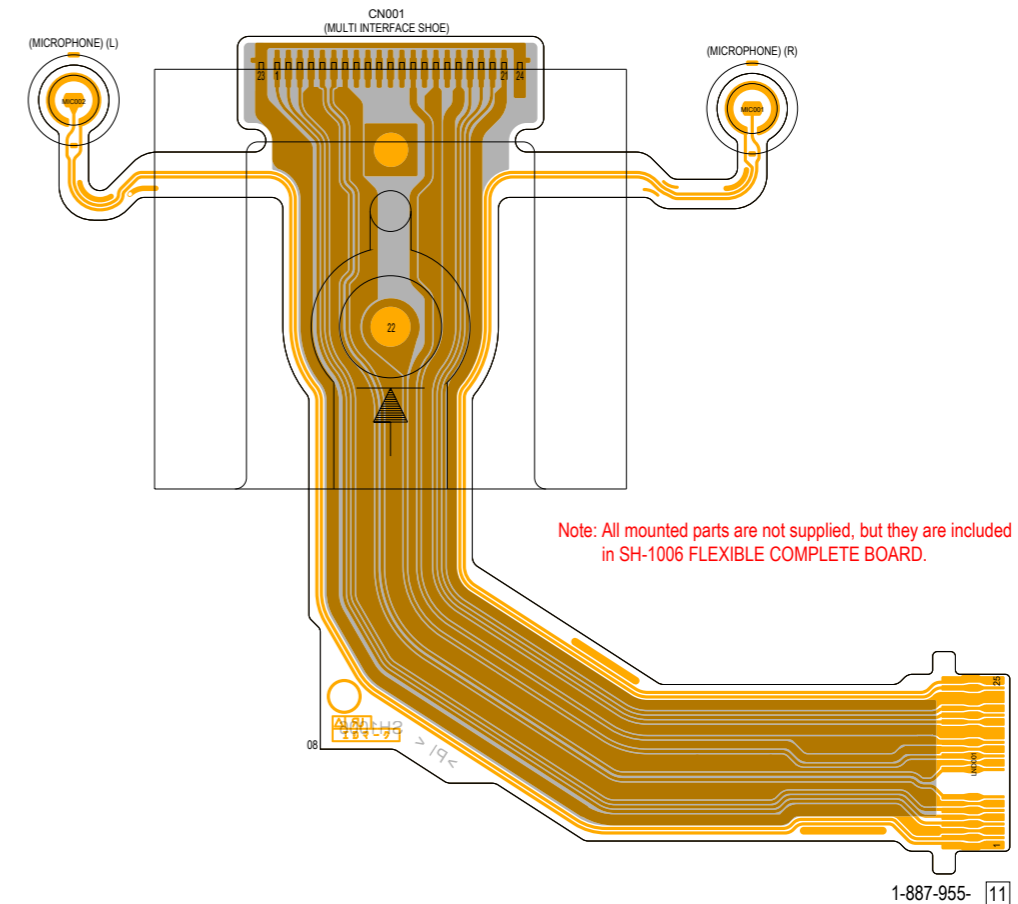
CD-1005 FLEXIBLE BOARD



Note: All mounted parts are not supplied, but they are included in CD-1005 FLEXIBLE COMPLETE BOARD.

1-887-947- 11

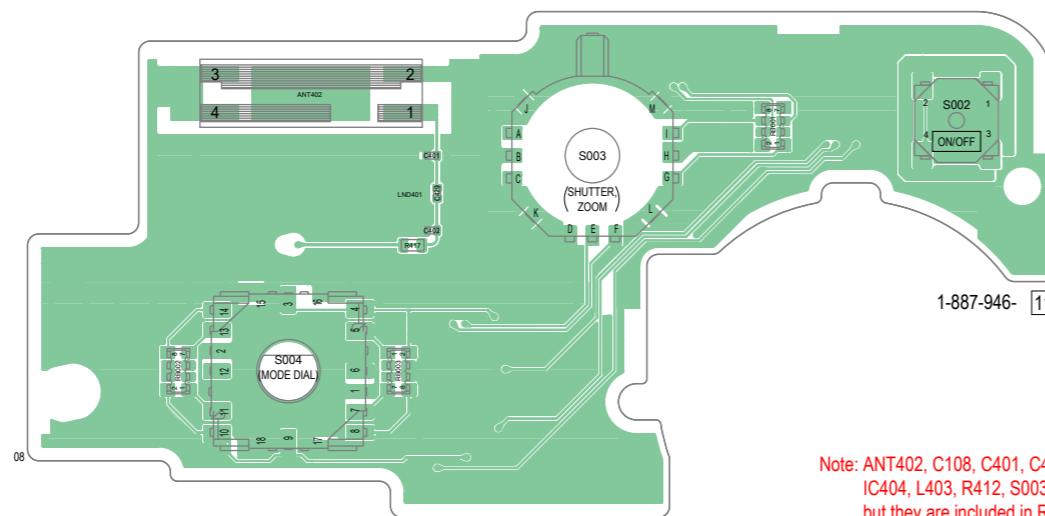
SH-1006 FLEXIBLE BOARD



Note: All mounted parts are not supplied, but they are included in SH-1006 FLEXIBLE COMPLETE BOARD.

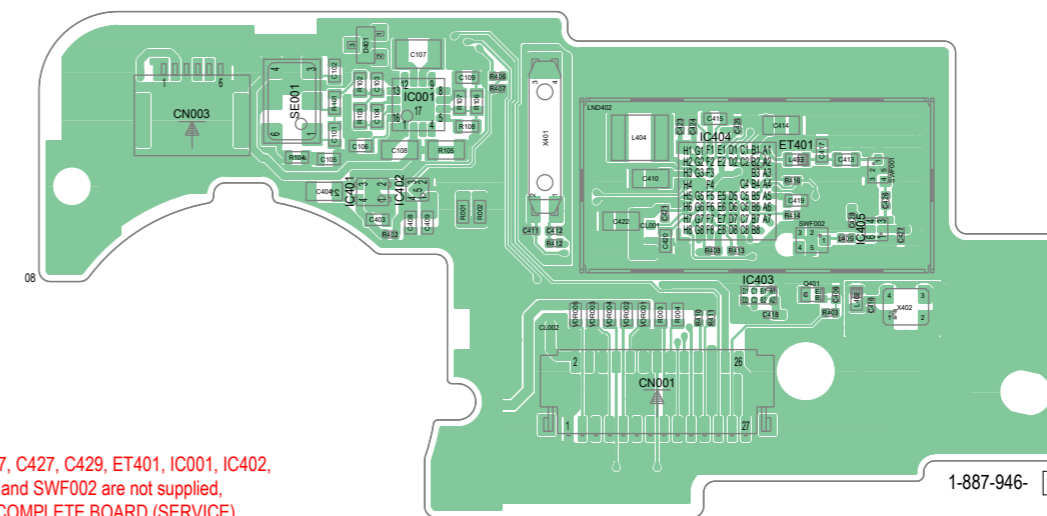
1-887-955- 11

RL-1011 BOARD (SIDE A)



1-887-946- 11

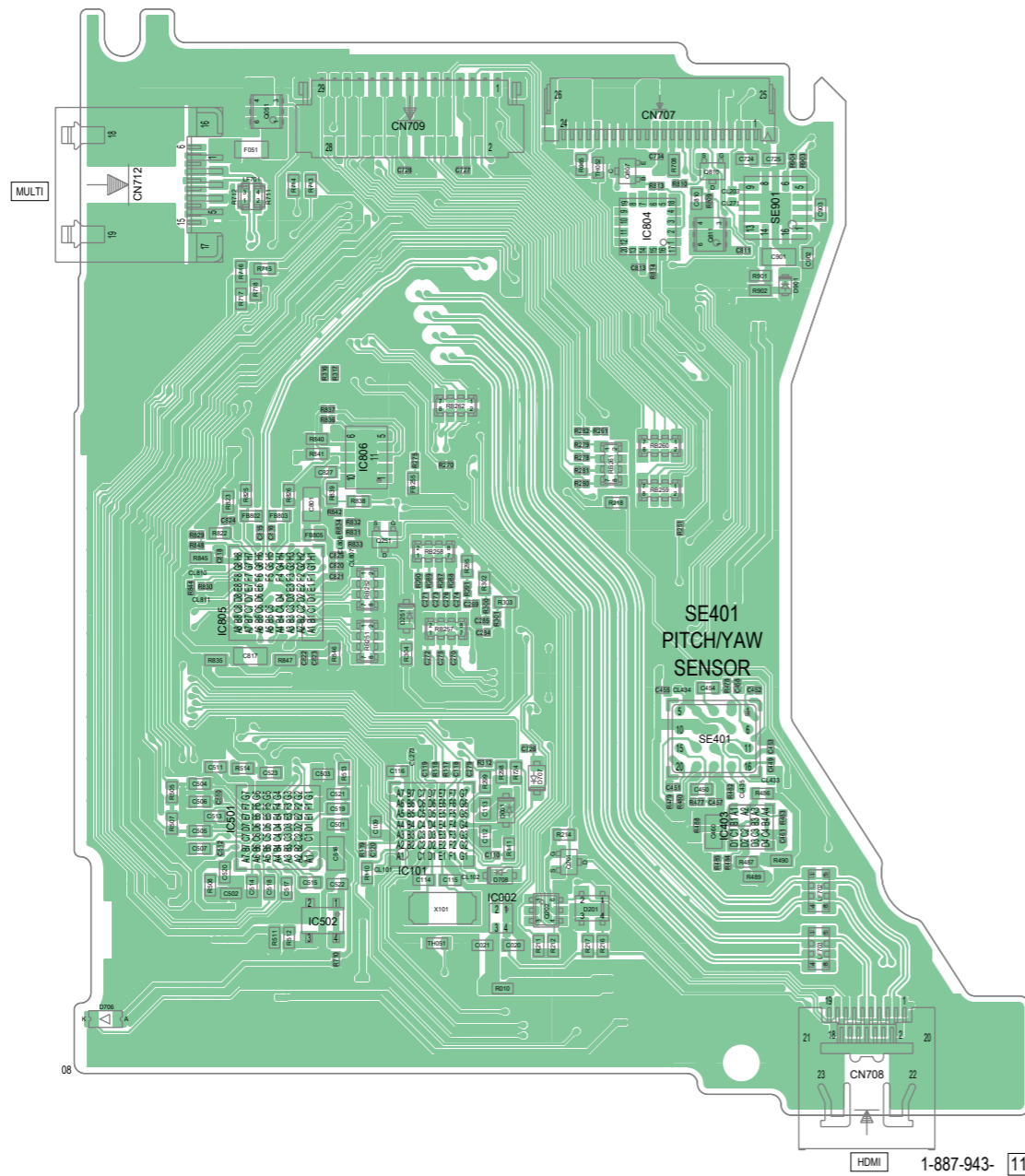
RL-1011 BOARD (SIDE B)



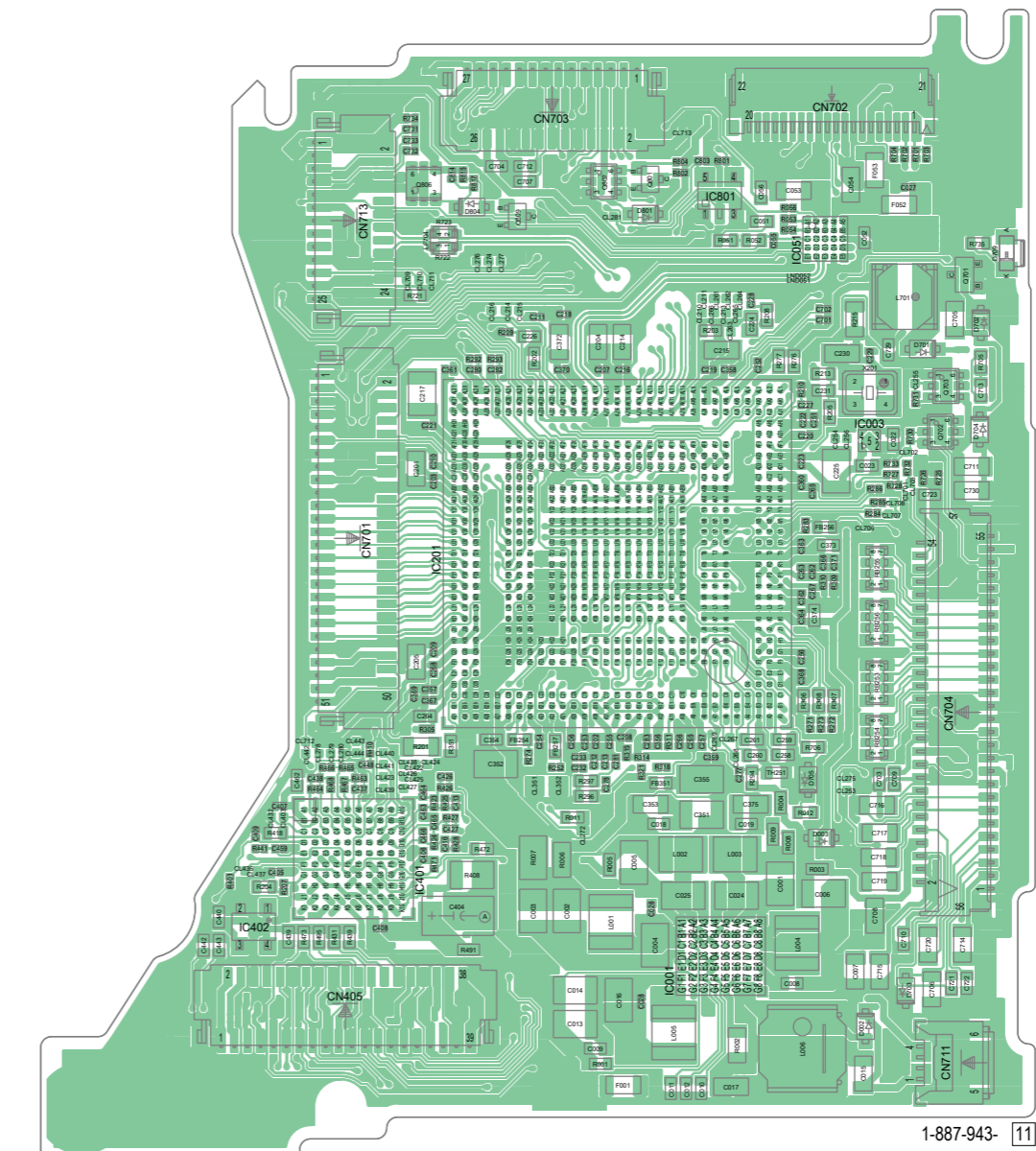
1-887-946- 11

Note: ANT402, C108, C401, C416, C417, C427, C429, ET401, IC001, IC402, IC404, L403, R412, S003, SE001 and SWF002 are not supplied, but they are included in RL-1011 COMPLETE BOARD (SERVICE).

SY-1018 BOARD (SIDE A)

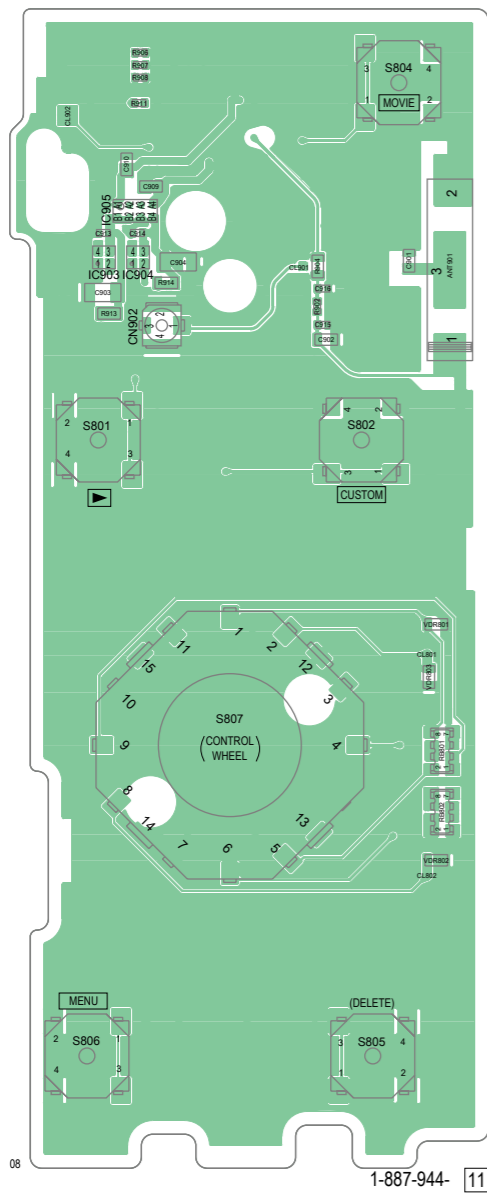


SY-1018 BOARD (SIDE B)

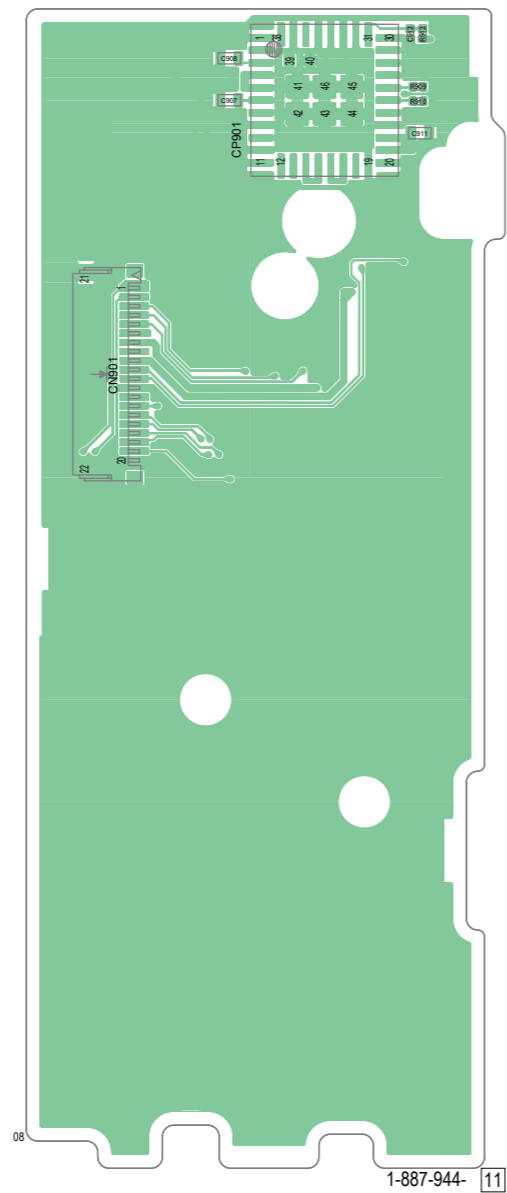


Note: C015, C212, C213, C225, C232, C233, C359, C366, C367, C371, C449, C451, C504, C505, C706, C708, C709, C710, C713, C716, C717, C718, C719, C720, C722, C723, C824, CN704, CN711, CN712, D002, D709, IC001, IC002, IC051, IC201, IC402, IC801, IC805, L002, L003, L005 and L701 are not supplied, but they are included in SY-1018 COMPLETE BOARD (SERVICE).

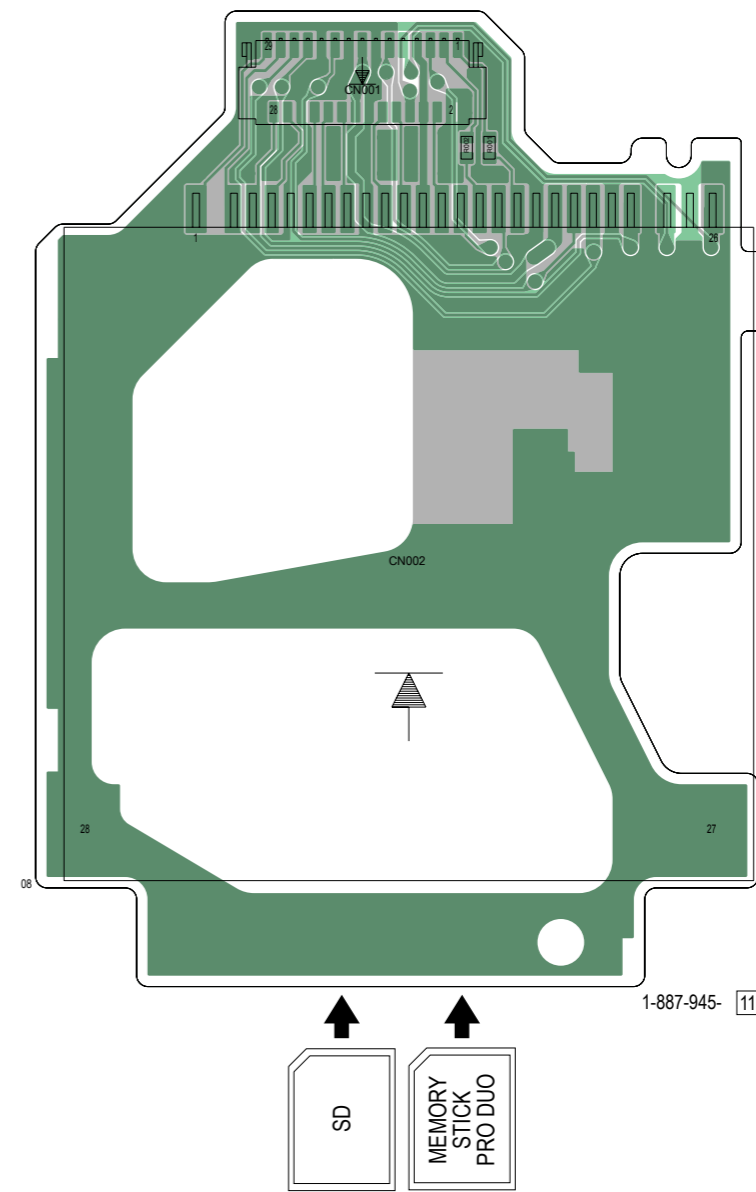
SW-1006 BOARD (SIDE A)



SW-1006 BOARD (SIDE B)

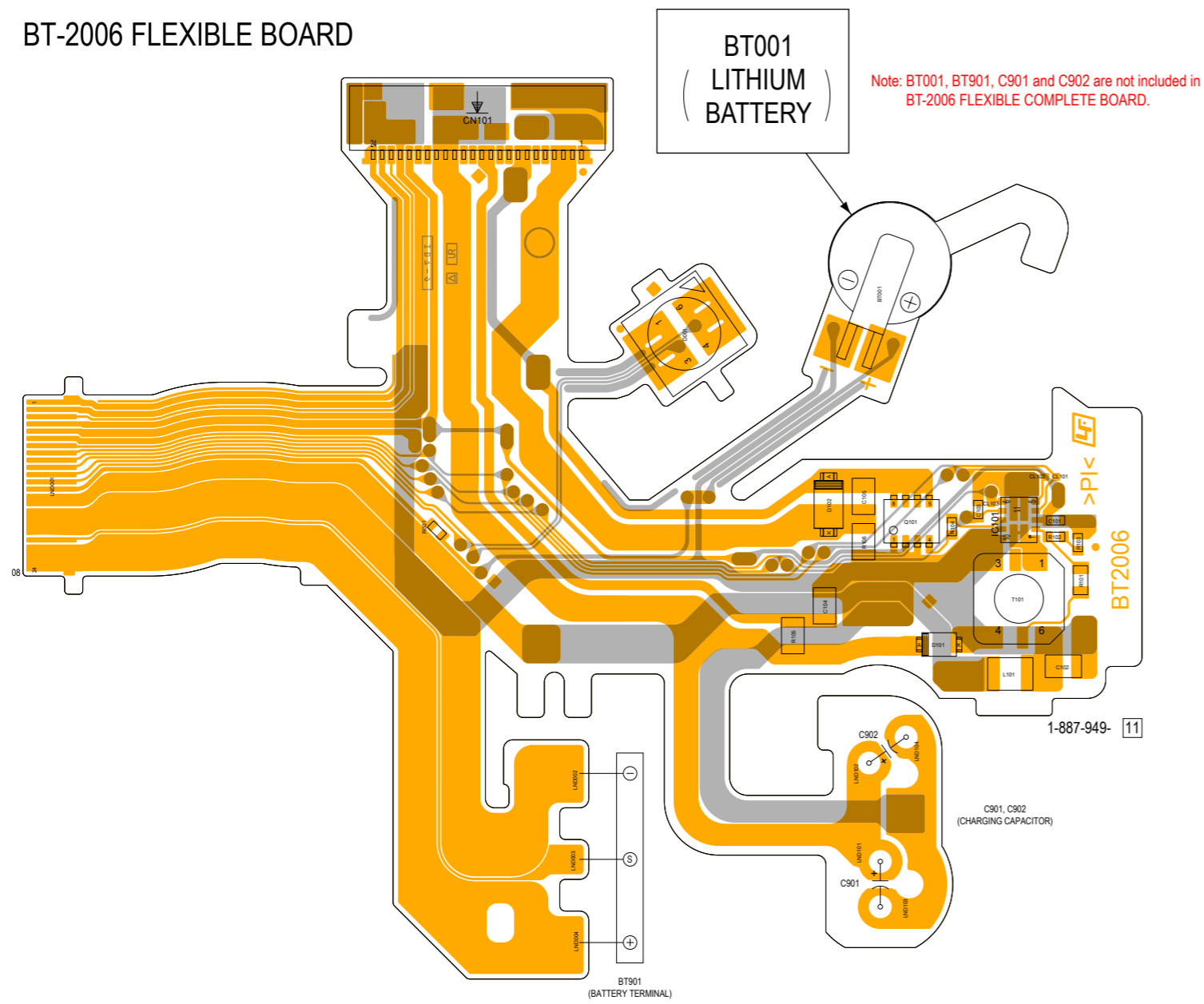


MS-1013 BOARD



Note: ANT901, C913, C914, CP901 and IC905 are not supplied, but they are included in SW-1006 COMPLETE BOARD.

BT-2006 FLEXIBLE BOARD



BT001
(LITHIUM BATTERY)

Note: BT001, BT901, C901 and C902 are not included in BT-2006 FLEXIBLE COMPLETE BOARD.

1-887-949-11

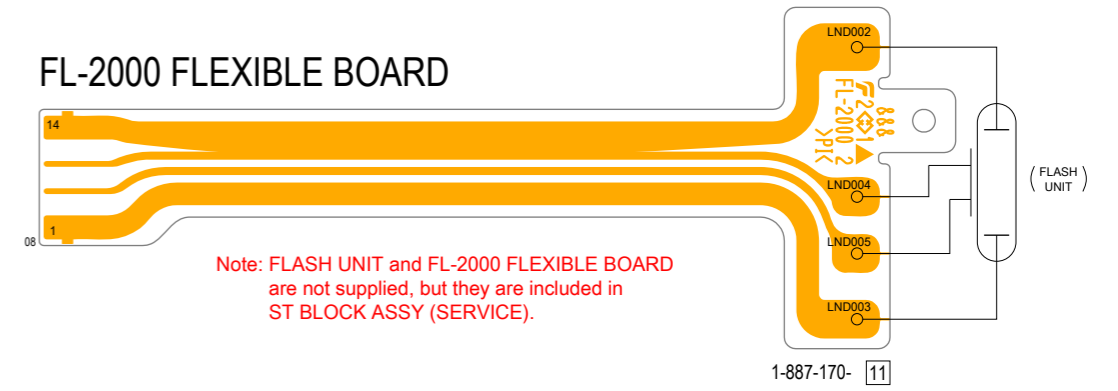
C901, C902
(CHARGING CAPACITOR)

BT901
(BATTERY TERMINAL)

Caution
Danger of explosion if battery is incorrectly replaced.
Replace only with the same or equivalent type.
Dispose of used batteries according to the instructions.

注意
電池の交換は、正しく行わないと破裂する恐れがあります。
電池を交換する場合には必ず同じ型名の電池又は同等品と交換してください。
使用済み電池は、取扱指示に従って処分してください。

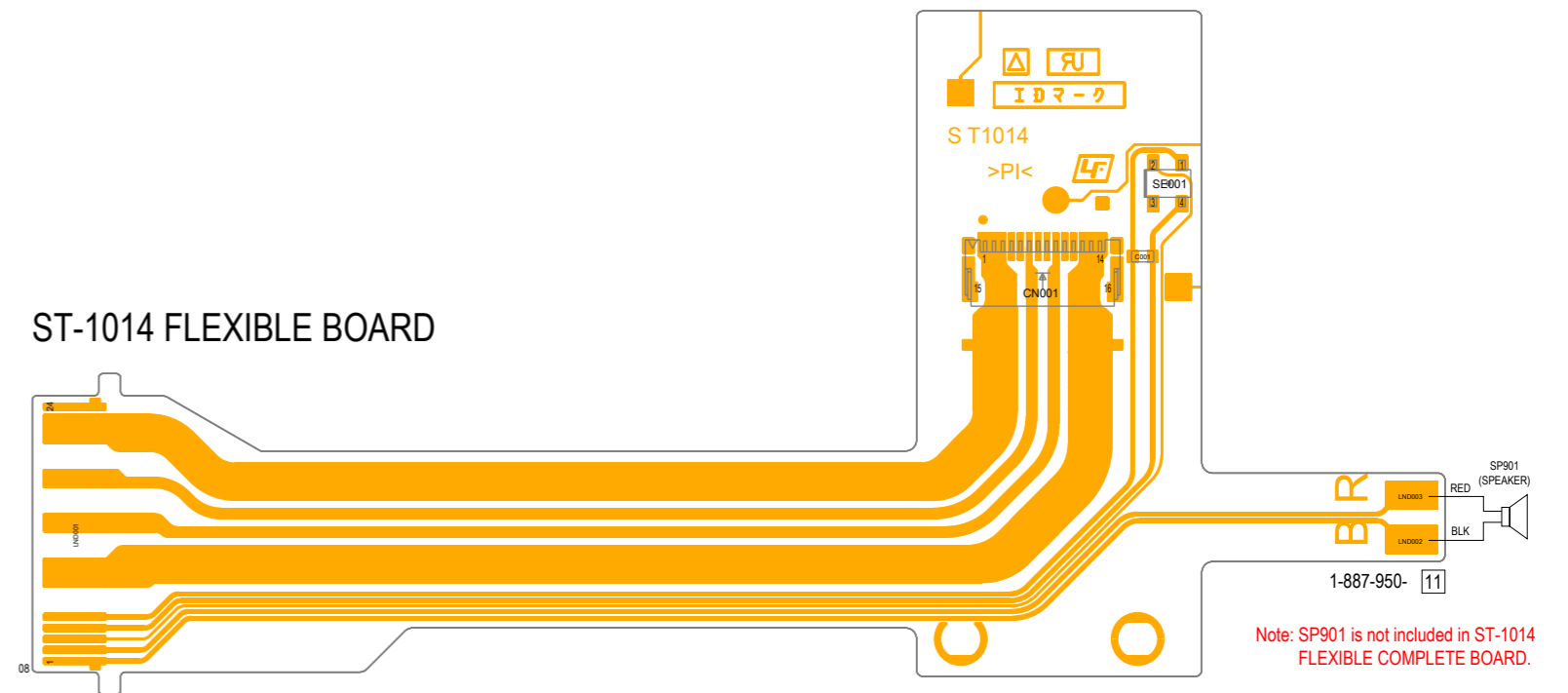
FL-2000 FLEXIBLE BOARD



Note: FLASH UNIT and FL-2000 FLEXIBLE BOARD are not supplied, but they are included in ST BLOCK ASSY (SERVICE).

1-887-170-11

ST-1014 FLEXIBLE BOARD



1-887-950-11

Note: SP901 is not included in ST-1014 FLEXIBLE COMPLETE BOARD.